

# Error Analysis and Management for MLC NAND Flash Memory

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(joint work with Yu Cai, Gulay Yalcin, Erich Haratsch, Ken Mai, Adrian Cristal, Osman Unsal)

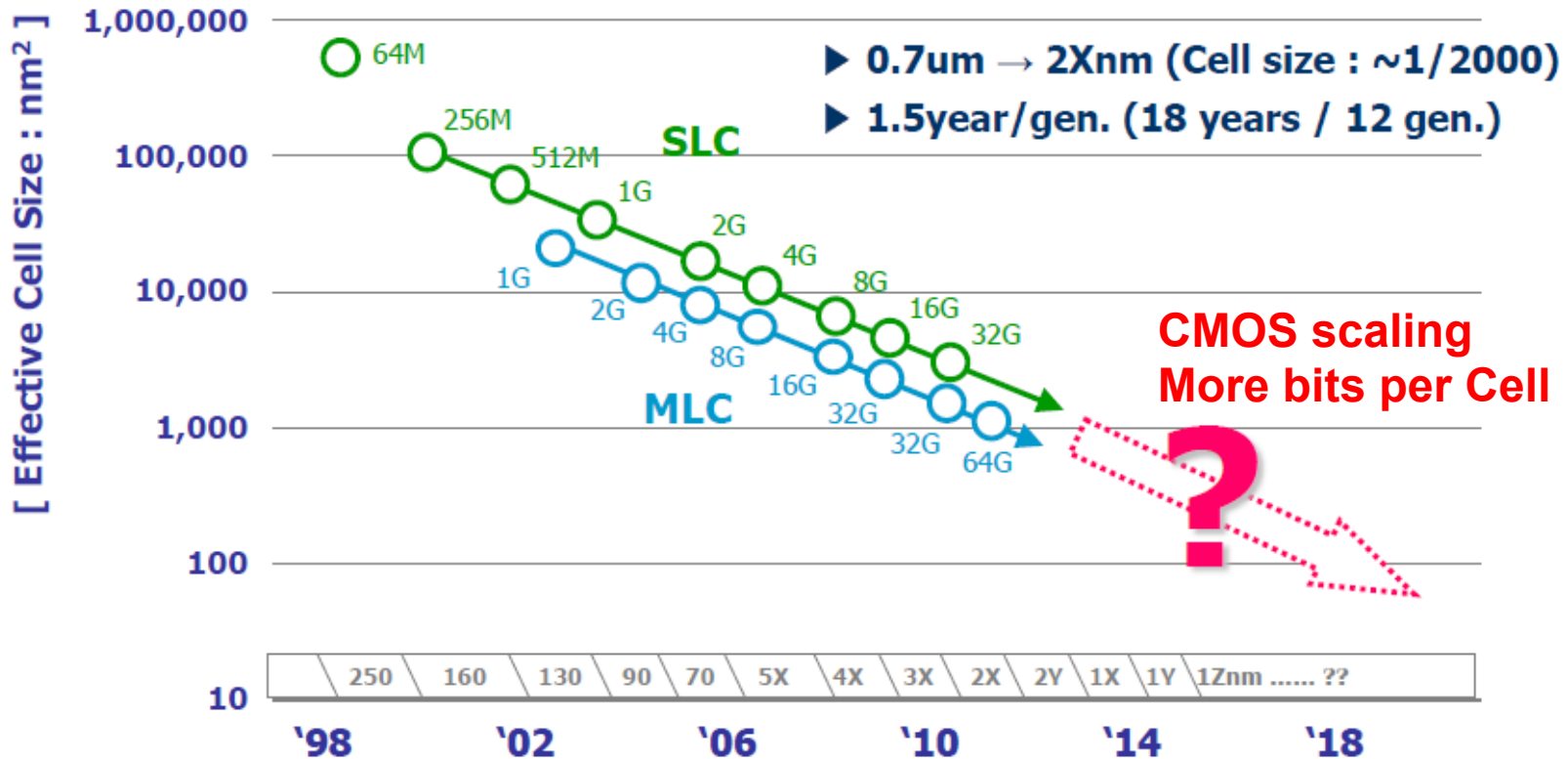
August 7, 2014

Flash Memory Summit 2014, Santa Clara, CA

- Problem: MLC NAND flash memory reliability/endurance is a key challenge for satisfying future storage systems' requirements
- Our Goals: (1) Build reliable error models for NAND flash memory via experimental characterization, (2) Develop efficient techniques to improve reliability and endurance
- This talk provides a “flash” summary of our recent results published in the past 3 years:
  - Experimental error and threshold voltage characterization [DATE'12&13]
  - Retention-aware error management [ICCD'12]
  - Program interference analysis and read reference V prediction [ICCD'13]
  - Neighbor-assisted error correction [SIGMETRICS'14]

- Background, Motivation and Approach
- Experimental Characterization Methodology
- Error Analysis and Management
  - Characterization Results
  - Retention-Aware Error Management
  - Threshold Voltage and Program Interference Analysis
  - Read Reference Voltage Prediction
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- Summary

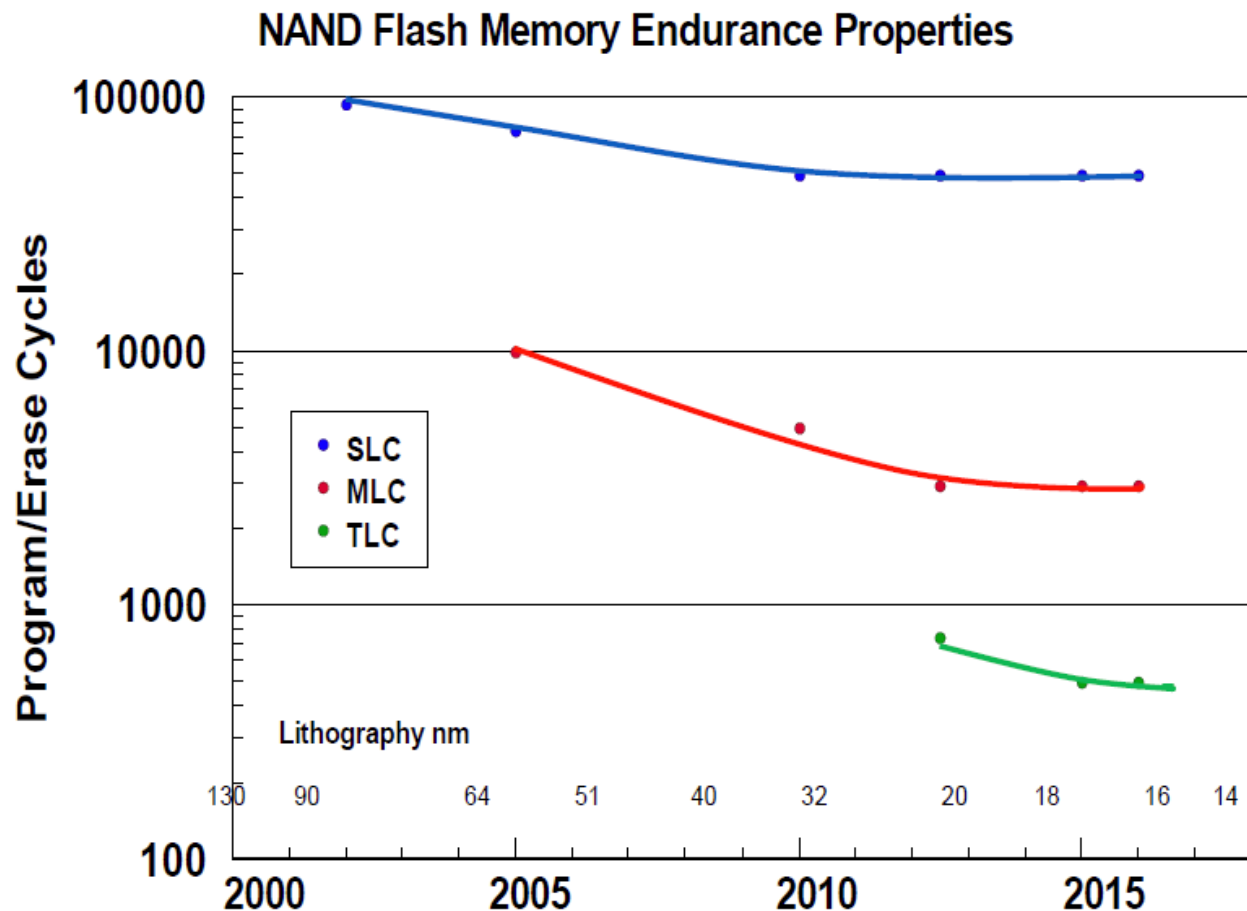
# Evolution of NAND Flash Memory



Seaung Suk Lee, "Emerging Challenges in NAND Flash Technology", Flash Summit 2011 (Hynix)

- Flash memory is widening its range of applications
  - Portable consumer devices, laptop PCs and enterprise servers

# Flash Challenges: Reliability and Endurance



E. Grochowski et al., "Future technology challenges for NAND flash and HDD products", Flash Memory Summit 2012

- **P/E cycles (provided)**

**A few thousand**

- **P/E cycles (required)**

Writing the full capacity of the drive  
10 times per day  
for 5 years  
(STEC)

**> 50k P/E cycles**

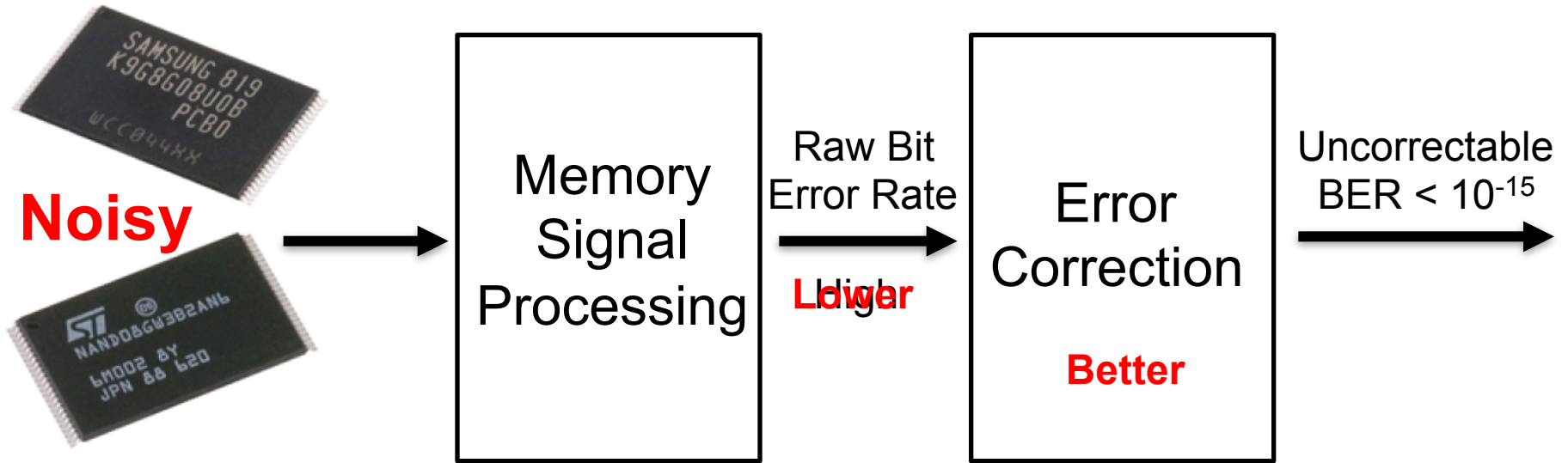
# NAND Flash Memory is Increasingly Noisy

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# Future NAND Flash-based Storage Architecture

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## Our Goals:

Build reliable error models for NAND flash memory

Design efficient reliability mechanisms based on the model

# NAND Flash Error Model



## Experimentally characterize and model dominant errors

Cai et al., “Error Patterns in MLC NAND Flash Memory: Measurement, Characterization, and Analysis”, **DATE 2012**



Cai et al., “Threshold voltage distribution in MLC NAND Flash Memory: Characterization, Analysis, and Modeling”, **DATE 2013**

Cai et al., “Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation”, **ICCD 2013**

Cai et al., “Flash Correct-and-Refresh: Retention-aware error management for increased flash memory lifetime”, **ICCD 2012**

Cai et al., “Neighbor-Cell Assisted Error Correction in MLC NAND Flash Memories”, **SIGMETRICS 2014**

Cai et al., “Error Analysis and Retention-Aware Error Management for NAND Flash Memory”, **ITJ 2013**



# Our Goals and Approach

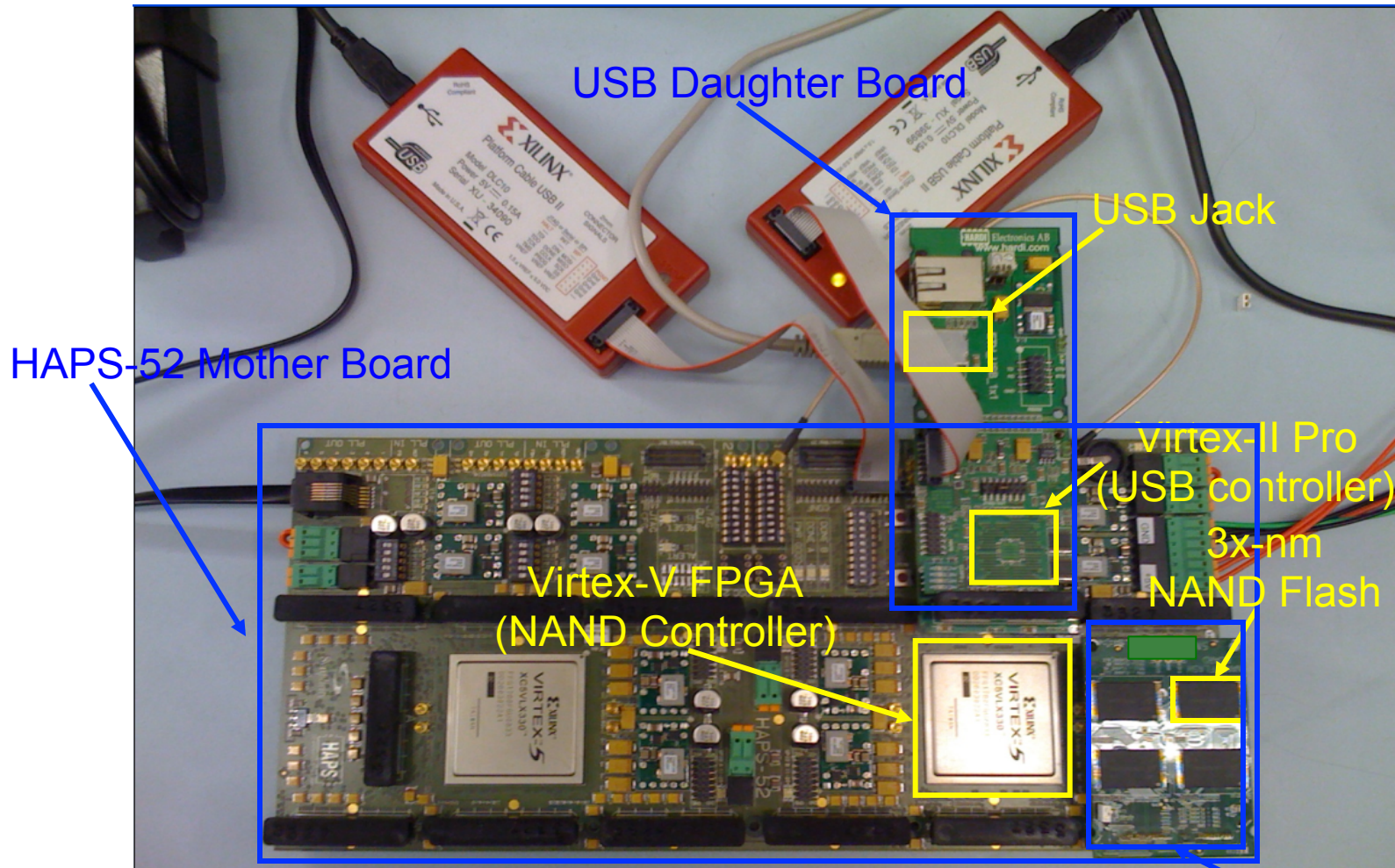
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- Goals:
  - Understand error mechanisms and develop reliable predictive models for MLC NAND flash memory errors
  - Develop efficient error management techniques to mitigate errors and improve flash reliability and endurance
  
- Approach:
  - Solid experimental analyses of errors in real MLC NAND flash memory → drive the understanding and models
  - Understanding, models and creativity → drive the new techniques

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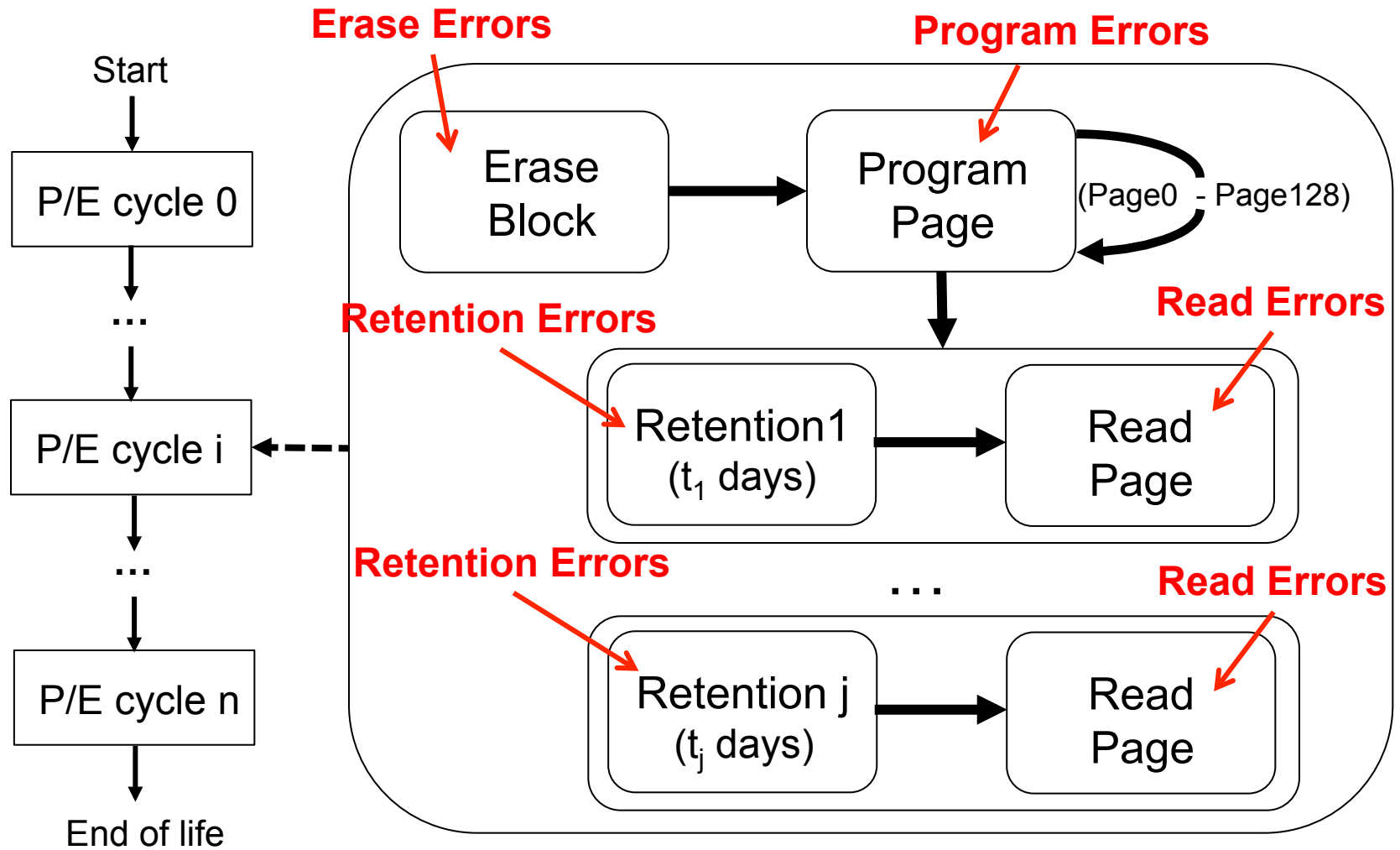
# Experimental Testing Platform



[Cai+, FCCM 2011, DATE 2012, ICCD 2012, DATE 2013, ITJ 2013, ICCD 2013, SIGMETRICS 2014]

NAND Daughter Board

# NAND Flash Usage and Error Model



# Methodology: Error and ECC Analysis

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- **Characterized errors and error rates** of 3x and 2y-nm MLC NAND flash using an experimental FPGA-based platform
  - [Cai+, DATE'12, ICCD'12, DATE'13, ITJ'13, ICCD'13, SIGMETRICS'14]
- **Quantified Raw Bit Error Rate (RBER) at a given P/E cycle**
  - Raw Bit Error Rate: Fraction of erroneous bits without any correction
- **Quantified error correction capability** (and area and power consumption) of various BCH-code implementations
  - Identified how much RBER each code can tolerate
    - how many P/E cycles (flash lifetime) each code can sustain

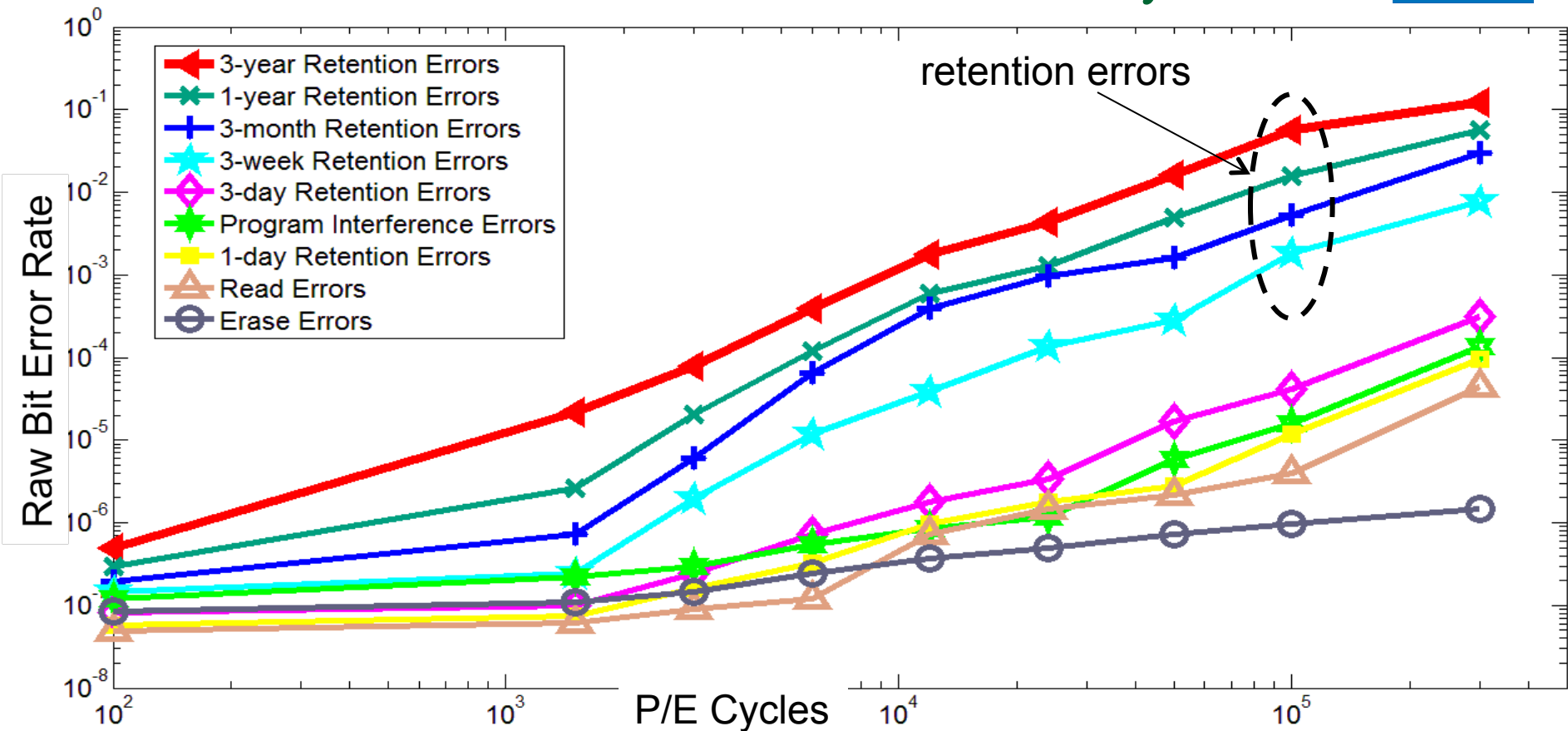
# NAND Flash Error Types

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- Four types of errors [Cai+, DATE 2012]
  
- Caused by **common flash operations**
  - Read errors
  - Erase errors
  - Program (interference) errors
  
- Caused by flash **cell losing charge over time**
  - Retention errors
    - Whether an error happens depends on required retention time
    - Especially problematic in MLC flash because threshold voltage window to determine stored value is smaller

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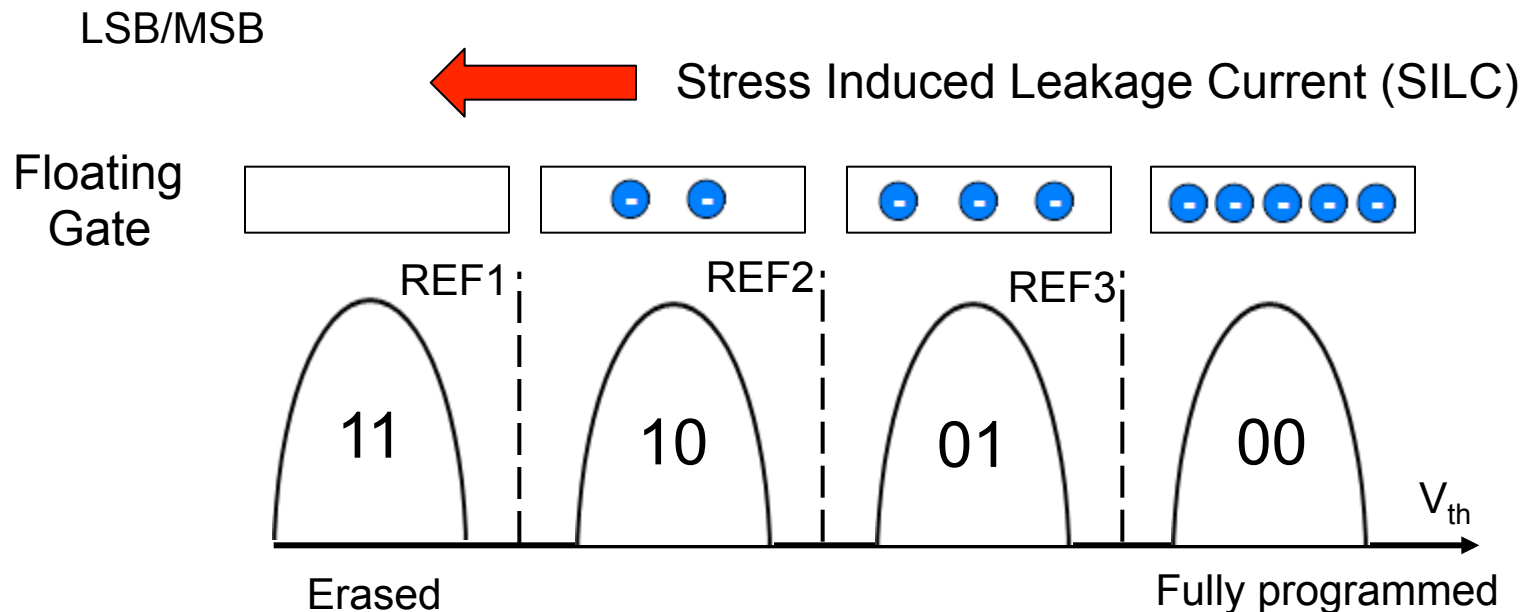
# Observations: Flash Error Analysis



- Raw bit error rate increases exponentially with P/E cycles
- Retention errors are dominant (>99% for 1-year ret. time)
- Retention errors increase with retention time requirement

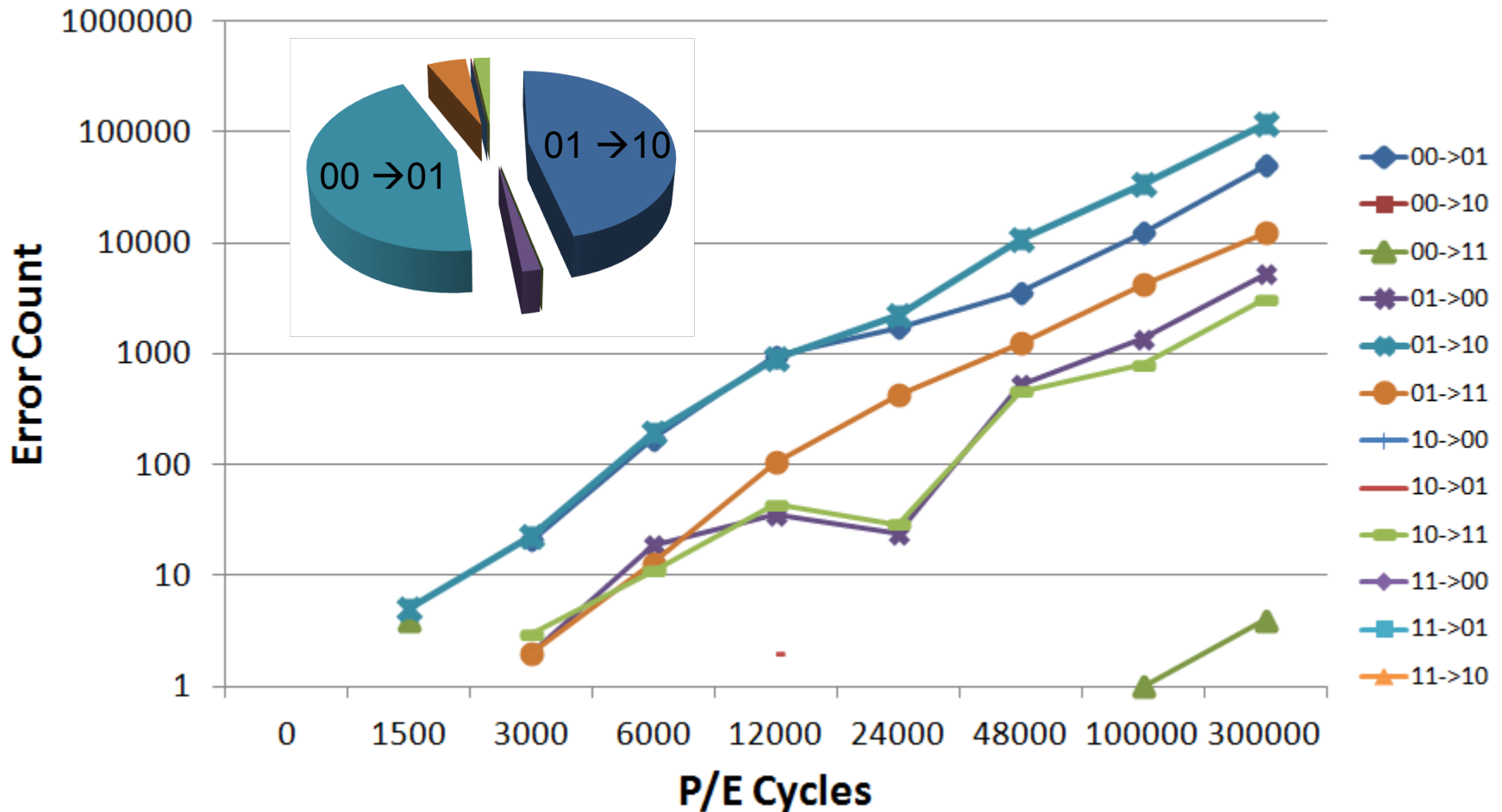


# Retention Error Mechanism



- Electron loss from the floating gate causes retention errors
  - ❑ Cells with more programmed electrons suffer more from retention errors
  - ❑ Threshold voltage is more likely to shift by one window than by multiple

# Retention Error Value Dependency



- Cells with more programmed electrons tend to suffer more from retention noise (i.e. 00 and 01)

- Yu Cai, Erich F. Haratsch, Onur Mutlu, and Ken Mai, **"Error Patterns in MLC NAND Flash Memory: Measurement, Characterization, and Analysis"** *Proceedings of the Design, Automation, and Test in Europe Conference (DATE)*, Dresden, Germany, March 2012. [Slides \(ppt\)](#)

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# Flash Correct-and-Refresh (FCR)



## ■ Key Observations:

- ❑ Retention errors are the dominant source of errors in flash memory [Cai+ DATE 2012][Tanakamaru+ ISSCC 2011]  
→ limit flash lifetime as they increase over time
- ❑ Retention errors can be corrected by “refreshing” each flash page periodically

## ■ Key Idea:

- ❑ Periodically read each flash page,
- ❑ Correct its errors using “weak” ECC, and
- ❑ Either remap it to a new physical page or reprogram it in-place,
- ❑ Before the page accumulates more errors than ECC-correctable
- ❑ Optimization: Adapt refresh rate to endured P/E cycles

# FCR: Two Key Questions

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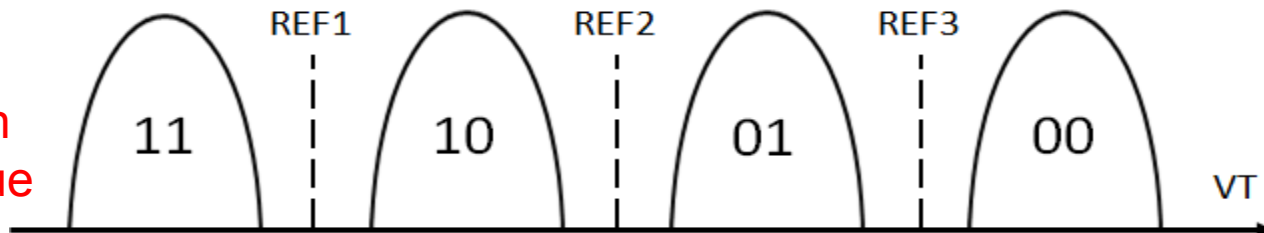
- How to refresh?
  - Remap a page to another one
  - Reprogram a page (in-place)
  - Hybrid of remap and reprogram
  
- When to refresh?
  - Fixed period
  - Adapt the period to retention error severity

# In-Place Reprogramming of Flash Cells

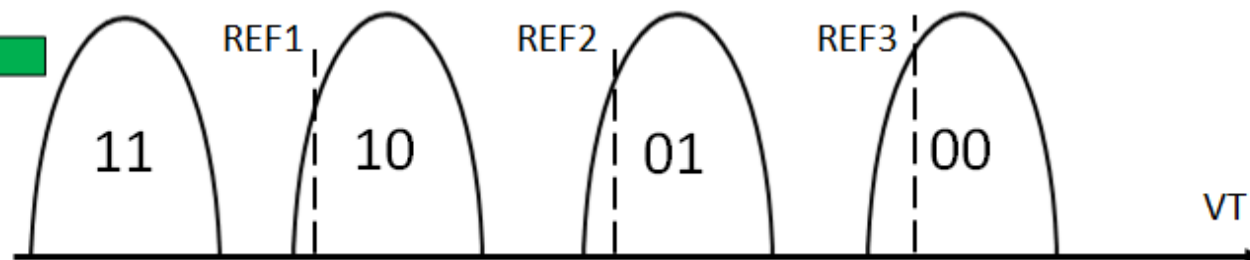
Floating Gate



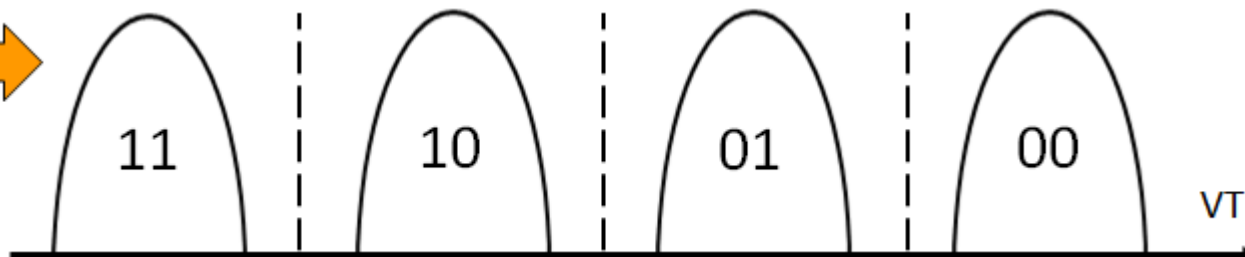
Floating Gate  
Voltage Distribution  
for each Stored Value



Retention errors are  
caused by cell voltage  
shifting to the left

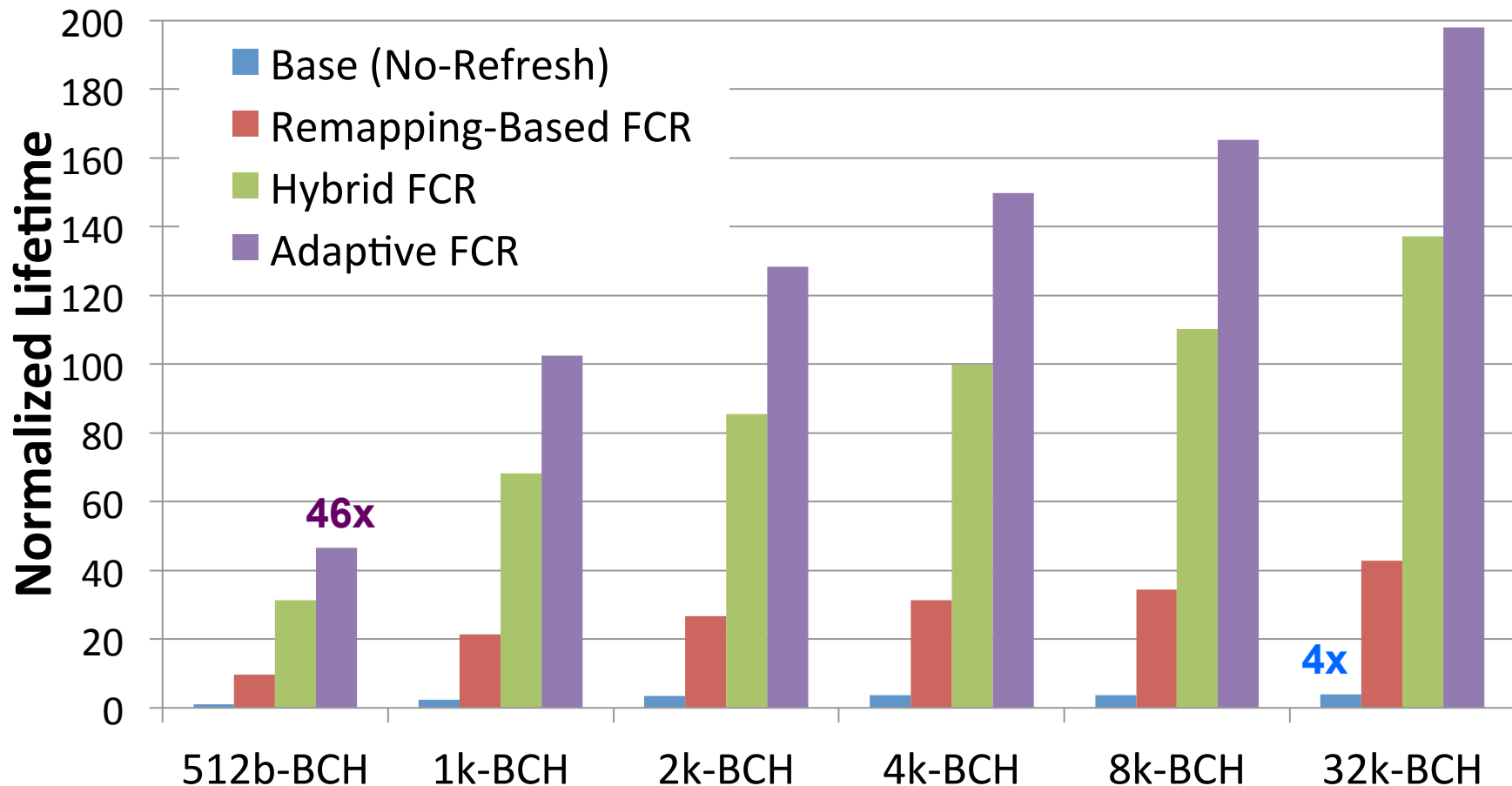


ISPP moves cell  
voltage to the right;  
fixes retention errors



- Pro: No remapping needed → no additional erase operations
- Con: Increases the occurrence of program errors

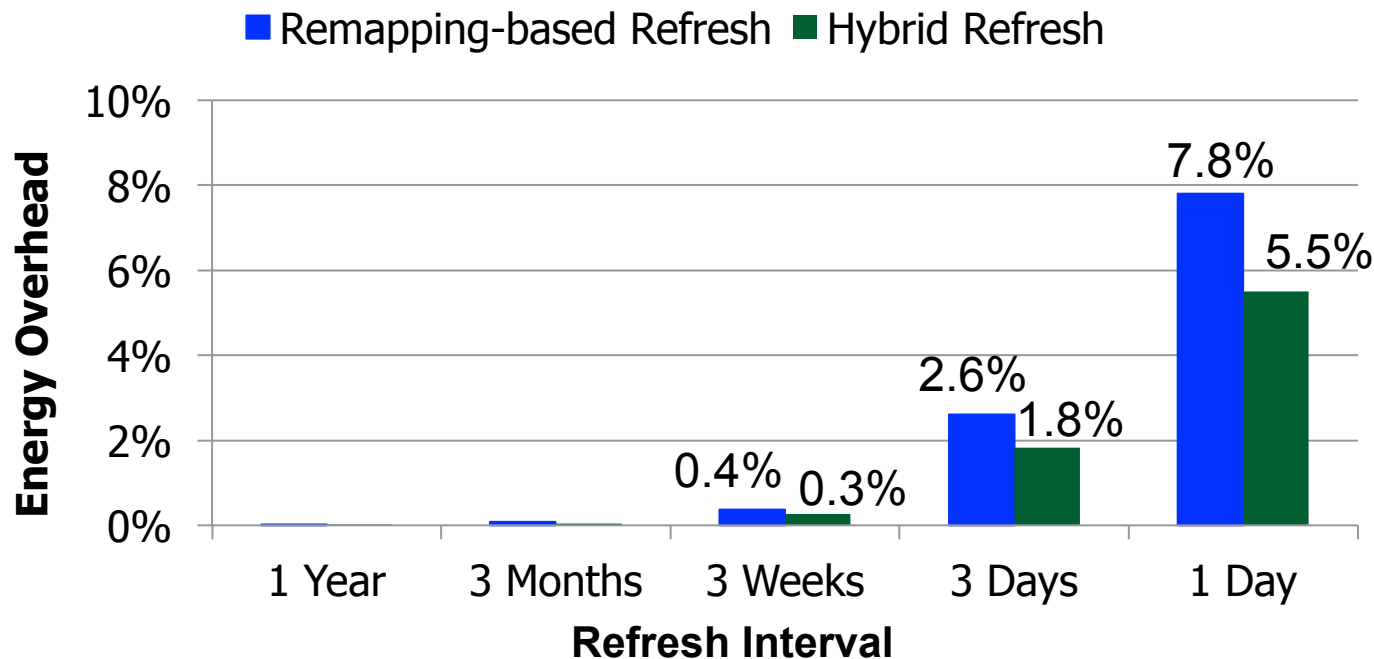
# Normalized Flash Memory Lifetime



Lifetime of FCR much higher than lifetime of stronger ECC



# Energy Overhead



- Adaptive-rate refresh: **<1.8%** energy increase until daily refresh is triggered

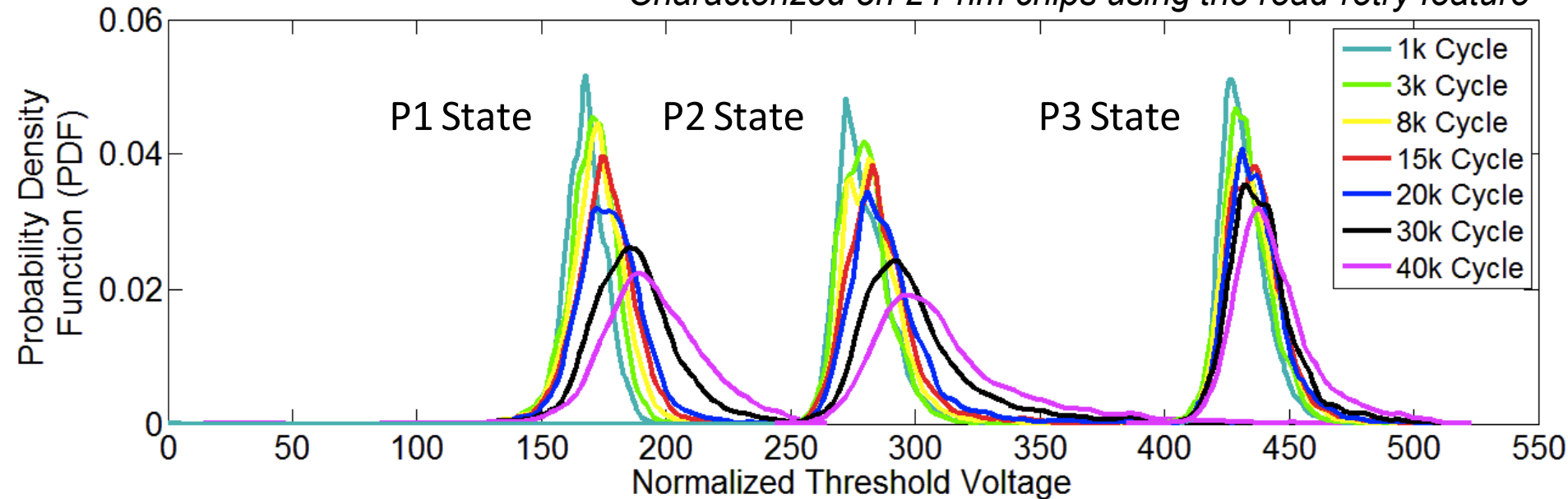
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- How does threshold voltage ( $V_{th}$ ) distribution of different programmed states change over flash lifetime?
- Can we model it accurately and predict the  $V_{th}$  changes?
- Can we build mechanisms that can correct for  $V_{th}$  changes? (thereby reducing read error rates)

# Threshold Voltage Distribution Model

*Characterized on 2Y-nm chips using the read-retry feature*



Gaussian distribution with additive white noise

As P/E cycles increase ...

- Distribution shifts to the right
- Distribution becomes wider

# Threshold Voltage Distribution Model

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- **V<sub>th</sub> distribution** can be modeled with ~95% accuracy as a **Gaussian distribution with additive white noise**
- **Distortion in V<sub>th</sub>** over P/E cycles can be modeled and predicted as **an exponential function of P/E cycles**
  - With more than 95% accuracy

# More Detail on Threshold Voltage Model

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- Yu Cai, Erich F. Haratsch, Onur Mutlu, and Ken Mai, **"Threshold Voltage Distribution in MLC NAND Flash Memory: Characterization, Analysis and Modeling"** *Proceedings of the Design, Automation, and Test in Europe Conference (DATE)*, Grenoble, France, March 2013. [Slides \(ppt\)](#)

# Program Interference Errors

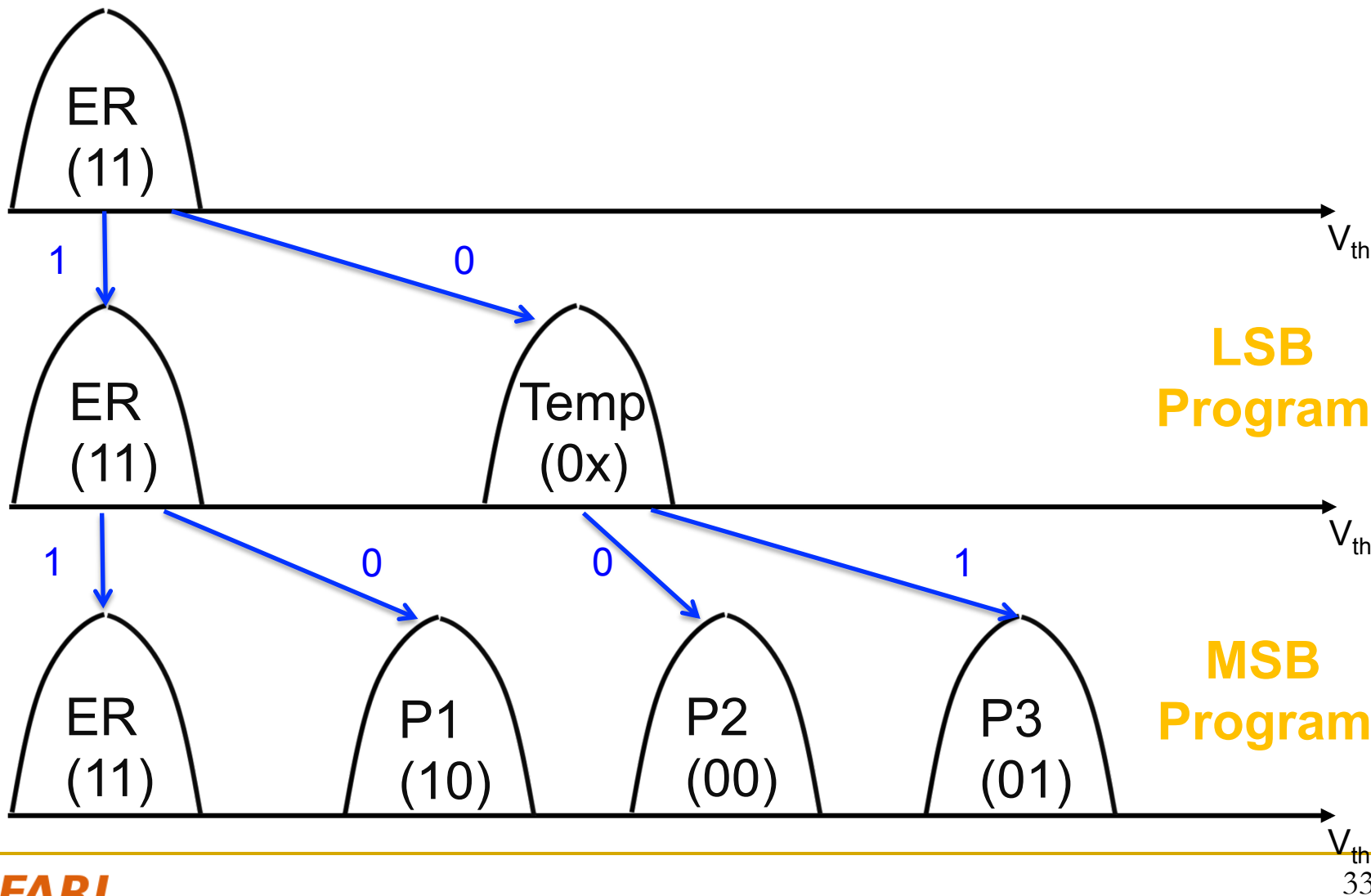
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- When a cell is being programmed, **voltage level of a neighboring cell changes** (unintentionally) due to parasitic capacitance coupling
  - **can change the data value stored**
- Also called program interference error
- Causes neighboring cell voltage to increase (shift right)
- Once retention errors are minimized, these errors can become dominant

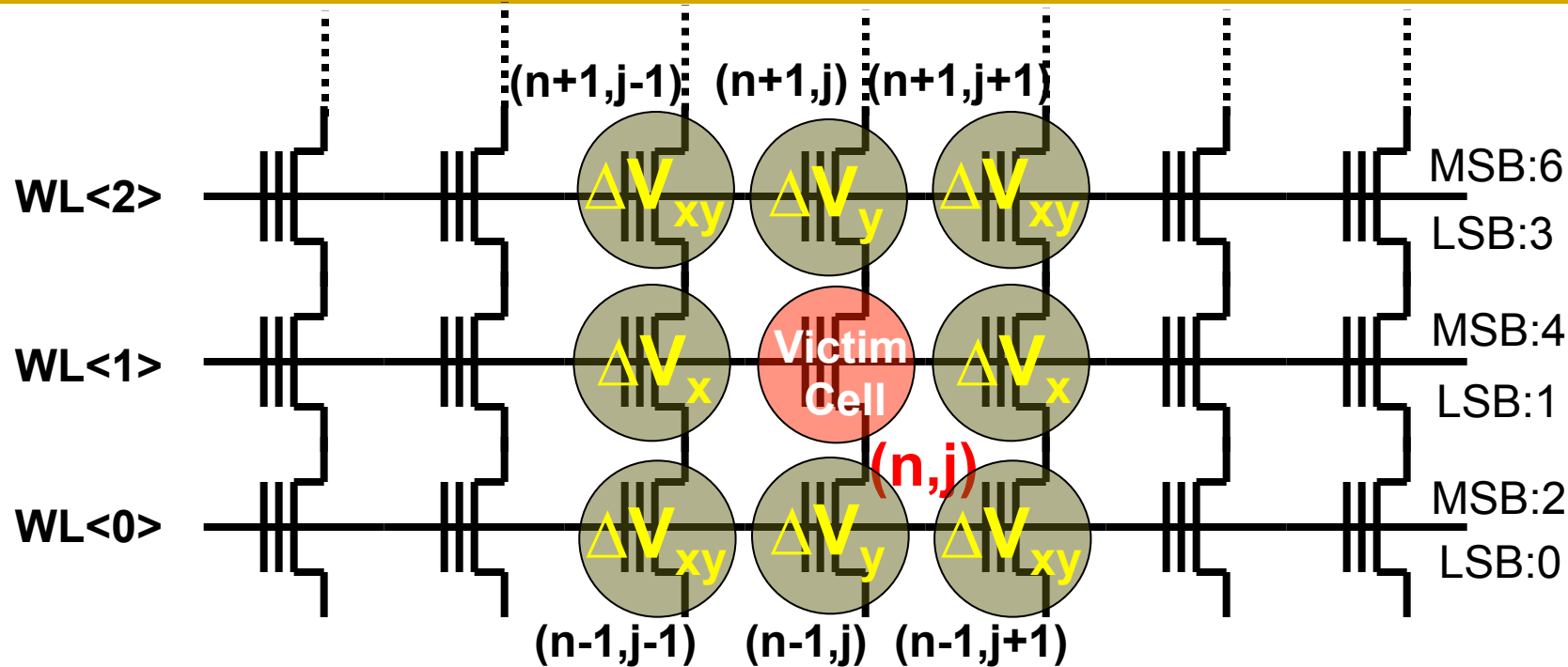


# How Current Flash Cells are Programmed

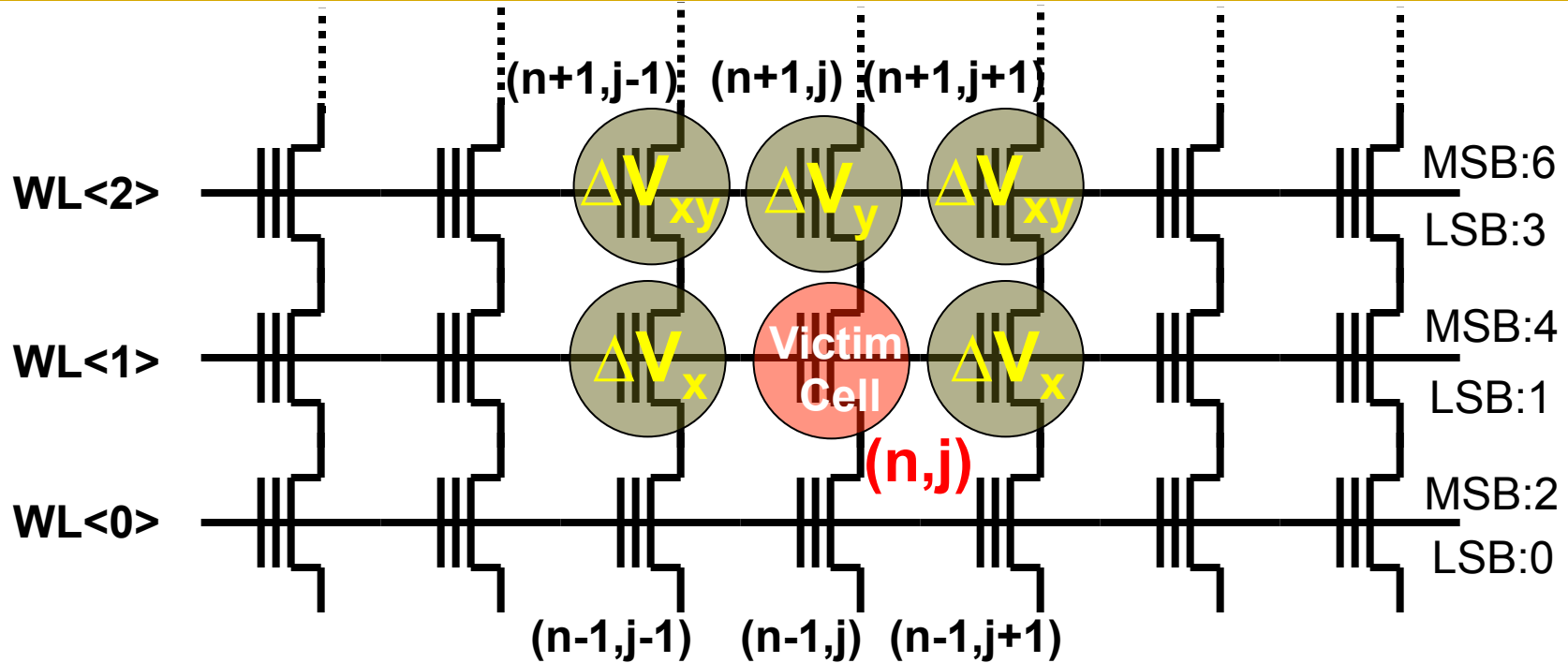
- Programming 2-bit MLC NAND flash memory in two steps



# Basics of Program Interference



# Traditional Model for $V_{th}$ Change



- Traditional model for victim cell threshold voltage change

$$\Delta V_{victim} = (2C_x \Delta V_x + C_y \Delta V_y + 2C_{xy} \Delta V_{xy}) / C_{total}$$

**Not accurate and requires knowledge of coupling caps!**

# Our Goal and Idea

- Develop a new, more accurate and easier to implement model for program interference
- Idea:
  - Empirically characterize and model the effect of neighbor cell  $V_{th}$  changes on the  $V_{th}$  of the victim cell
  - Fit neighbor  $V_{th}$  change to a linear regression model and find the coefficients of the model via empirical measurement

$$\Delta V_{victim}(n, j) = \sum_{y=j-K}^{j+K} \sum_{x=n+1}^{n=M} \alpha(x, y) \Delta V_{neighbor}(x, y) + \alpha_j V_{victim}^{before}(n, j)$$

Can be measured

# Developing a New Model via Empirical Measurement

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- Feature extraction for  $V_{th}$  changes based on characterization
  - Threshold voltage changes on aggressor cell
  - Original state of victim cell
- Enhanced linear regression model

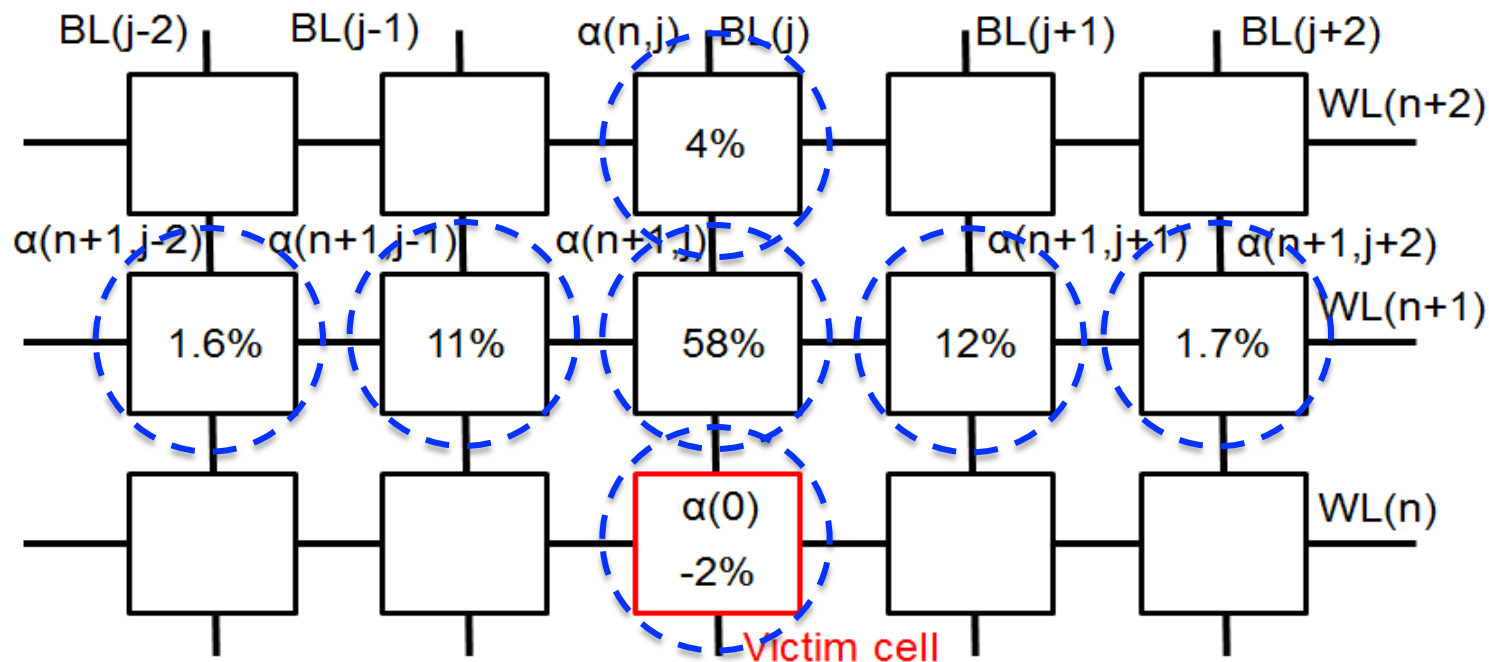
$$\Delta V_{victim}(n, j) = \sum_{y=j-K}^{j+K} \sum_{x=n+1}^{n=M} \alpha(x, y) \Delta V_{neighbor}(x, y) + \alpha_0 V_{victim}^{before}(n, j)$$

$$Y = X\alpha + \varepsilon \quad \leftarrow \text{(vector expression)}$$

- Maximum likelihood estimation of the model coefficients

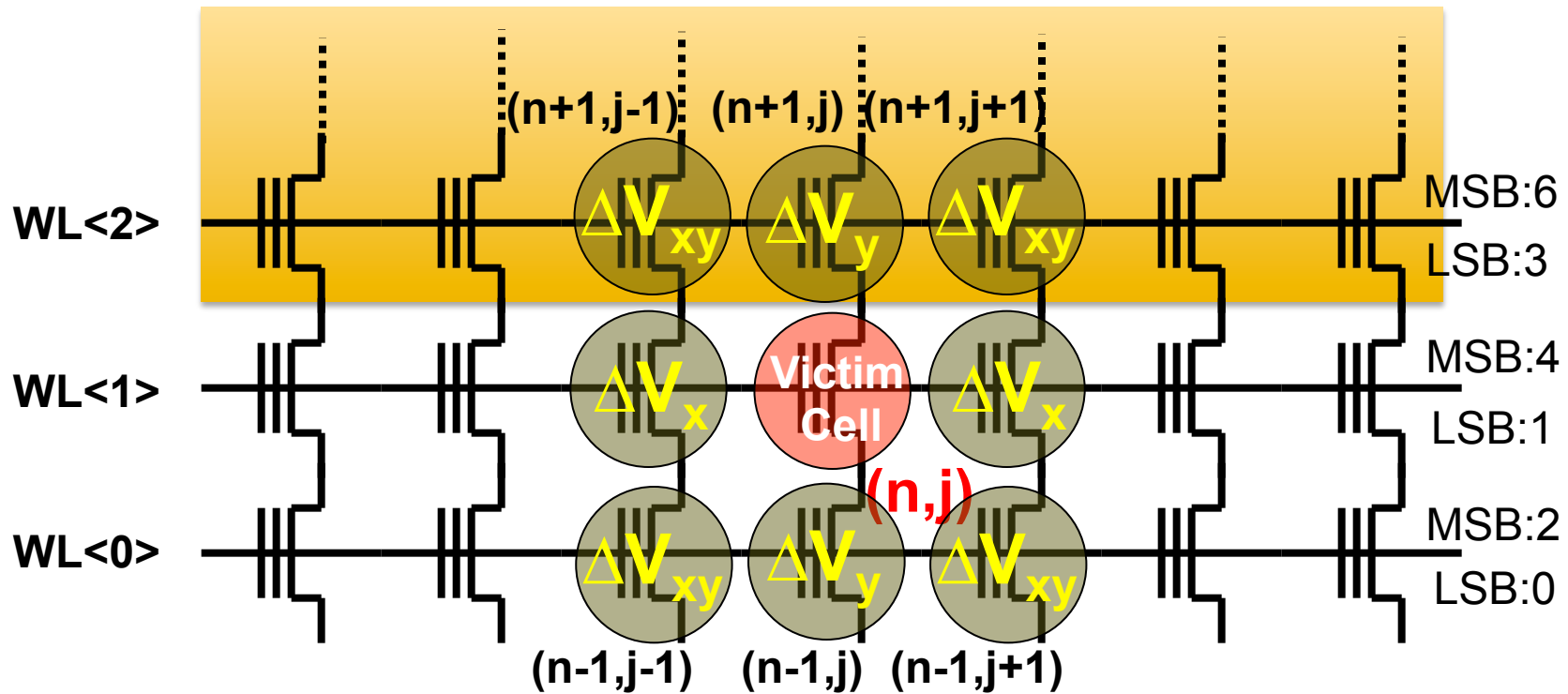
$$\arg \min_{\alpha} (\|X \times \alpha - Y\|_2^2 + \lambda \|\alpha\|_1)$$

# Effect of Neighbor Voltages on the Victim



- Immediately-above cell interference is dominant
- Immediately-diagonal neighbor is the second dominant
- Far neighbor cell interference exists
- Victim cell's  $V_{th}$  has negative effect on interference

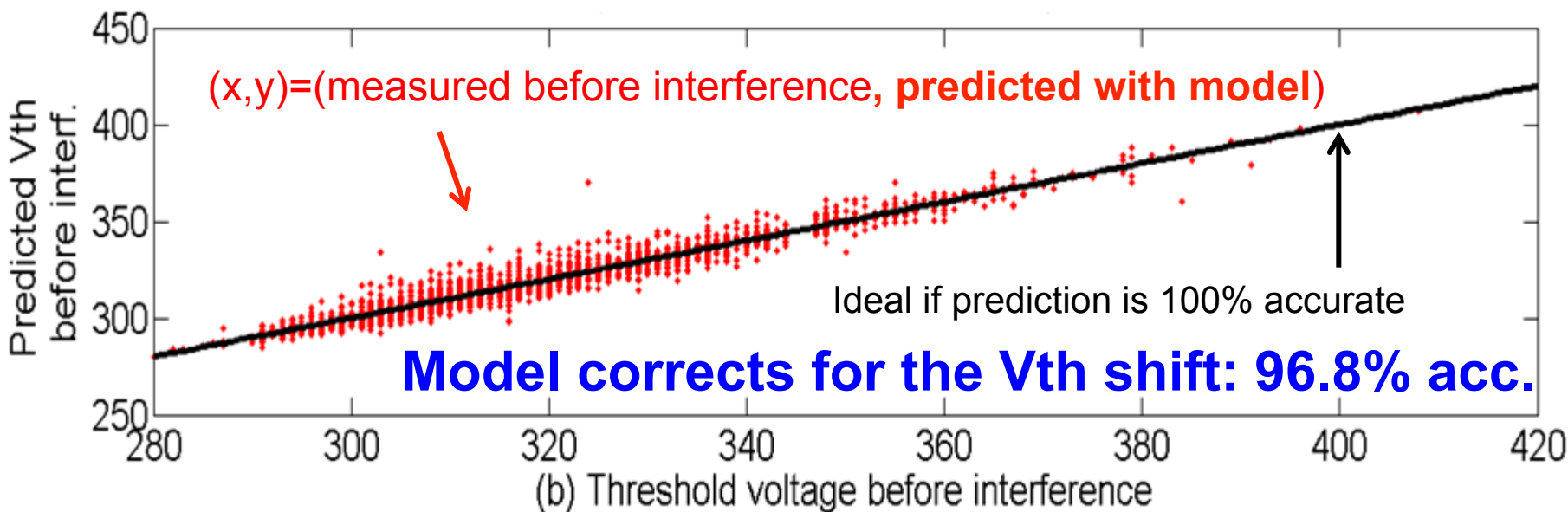
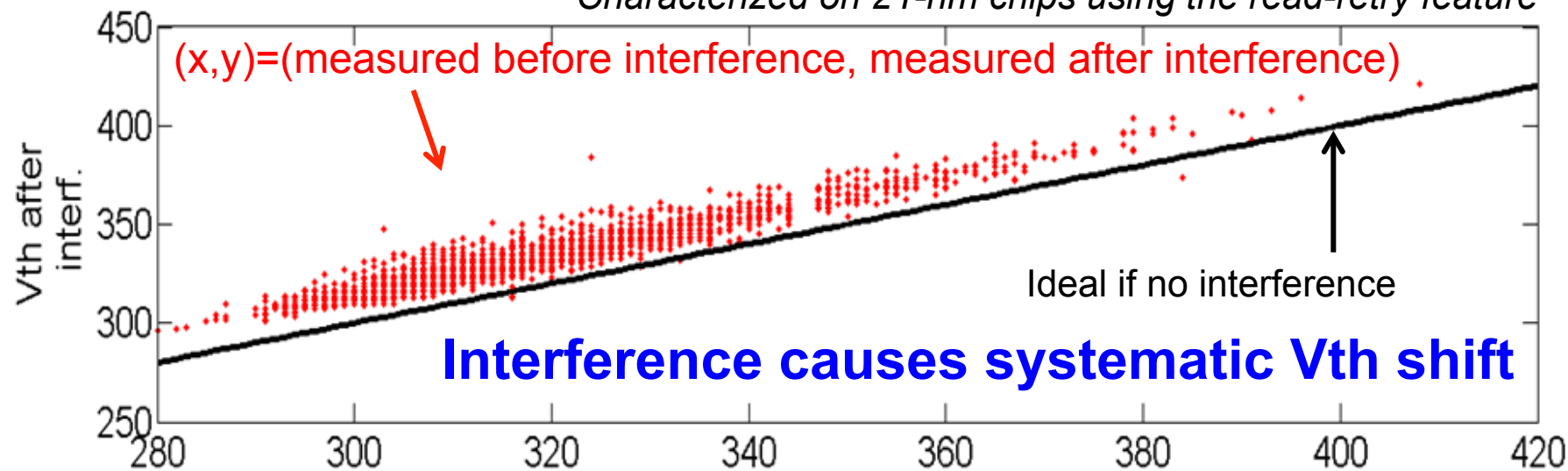
# New Model for Program Interference



$$\Delta V_{victim}(n, j) = \sum_{y=j-K}^{j+K} \sum_{x=n+1}^{n+M} \alpha(x, y) \Delta V_{neighbor}(x, y) + \alpha_0 V_{victim}^{before}(n, j)$$

# Model Accuracy

Characterized on 2Y-nm chips using the read-retry feature





# Many Other Results in the Paper

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- Yu Cai, Onur Mutlu, Erich F. Haratsch, and Ken Mai, **"Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation"**  
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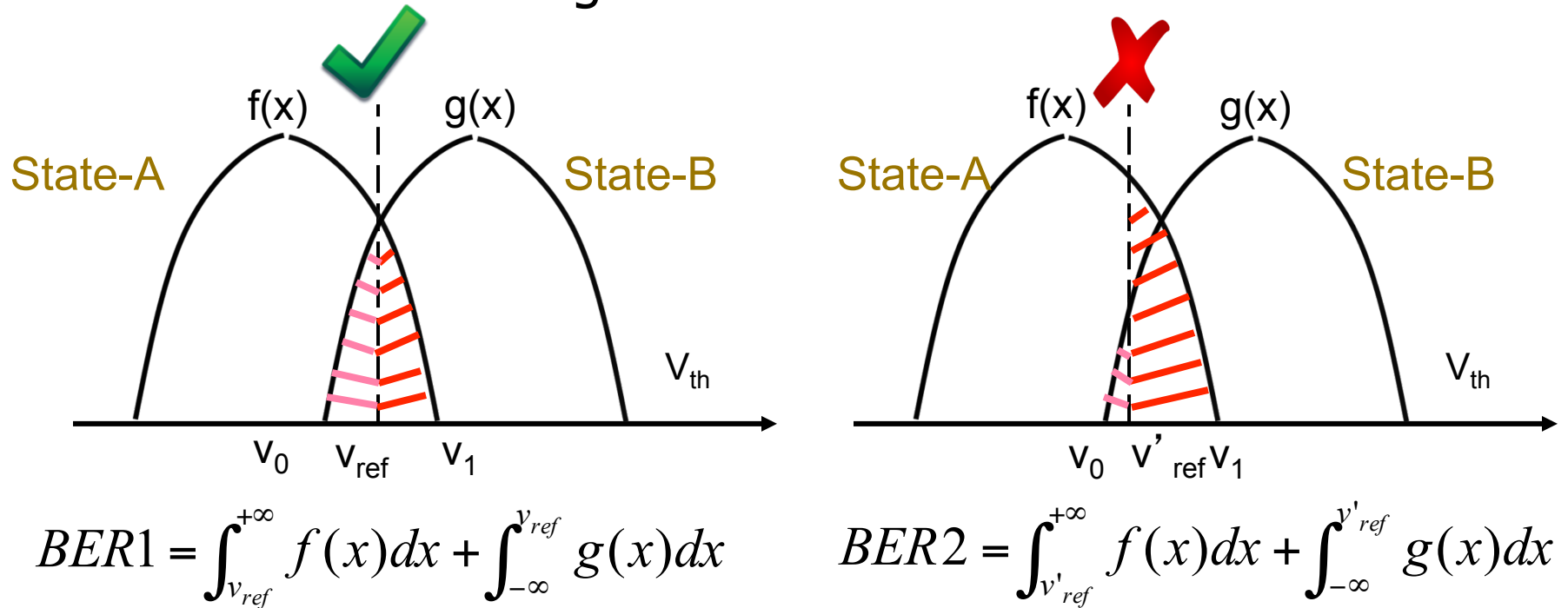
# Mitigation: Applying the Model

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- So, what can we do with the model?
- Goal: Mitigate the effects of program interference caused voltage shifts

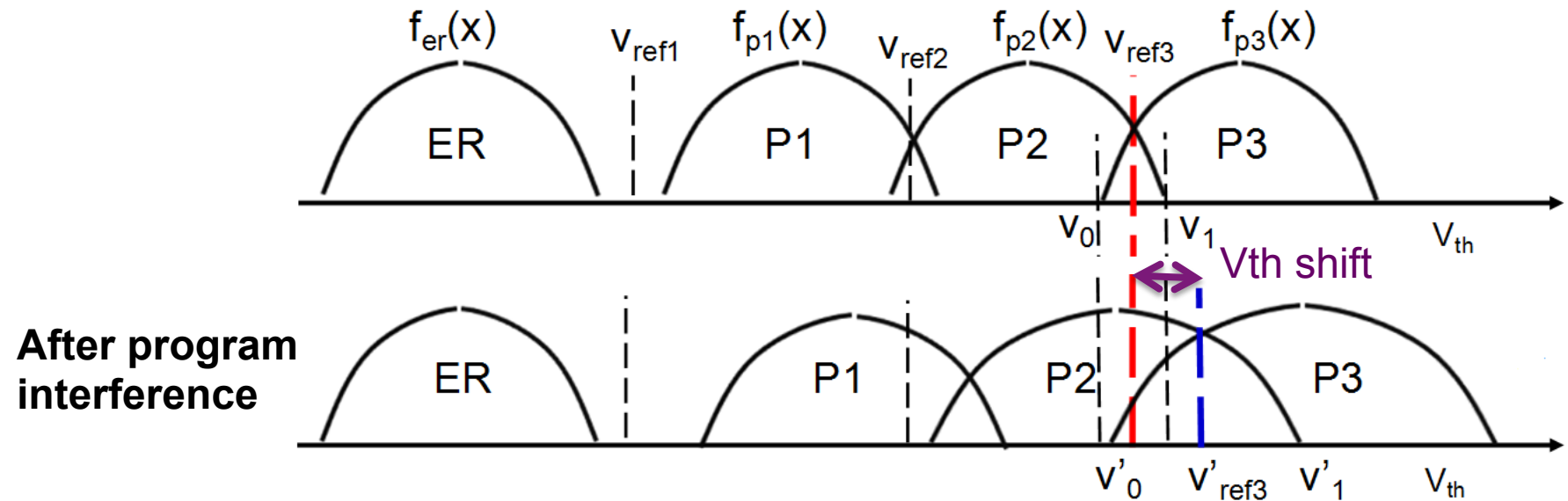
# Optimum Read Reference for Flash Memory

- Read reference voltage affects the raw bit error rate



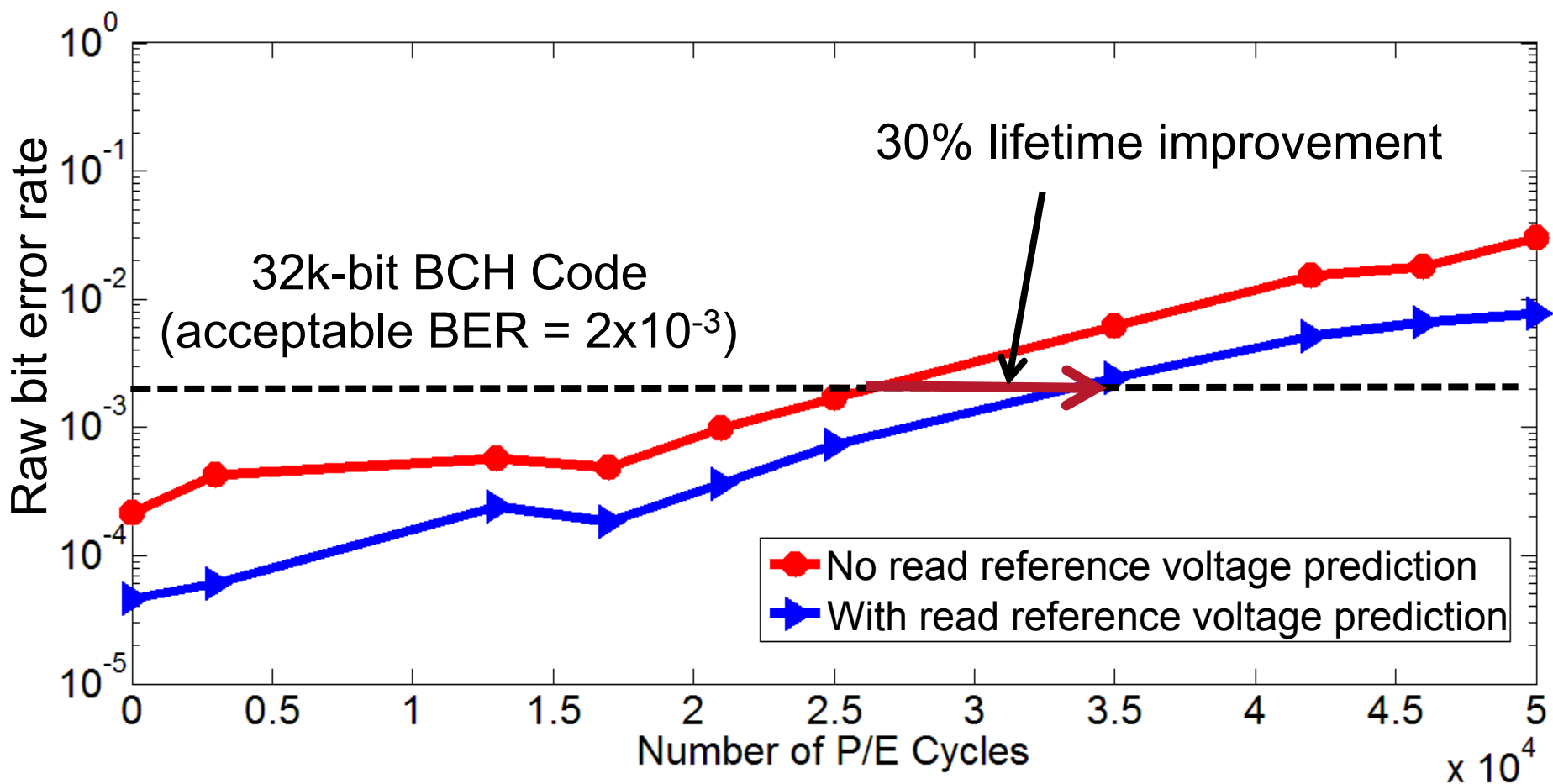
- There exists an optimal read reference voltage
  - Predictable if the statistics (i.e. mean, variance) of threshold voltage distributions are characterized and modeled

# Optimum Read Reference Voltage Prediction



- Vth shift learning (done every  $\sim 1k$  P/E cycles)
  - Program sample cells with known data pattern and test Vth
  - Program aggressor neighbor cells and test victim Vth after interference
  - Characterize the mean shift in Vth (i.e., program interference noise)
- Optimum read reference voltage prediction
  - Default read reference voltage + Predicted mean Vth shift by model

# Effect of Read Reference Voltage Prediction



- Read reference voltage prediction reduces raw BER (by 64%) and increases the P/E cycle lifetime (by 30%)

# More on Read Reference Voltage Prediction

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- Yu Cai, Onur Mutlu, Erich F. Haratsch, and Ken Mai, **"Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation"**  
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- Develop a better error correction mechanism for cases where ECC fails to correct a page

# Observations So Far

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- Immediate neighbor cell has the most effect on the victim cell when programmed
- A single set of read reference voltages is used to determine the value of the (victim) cell
- The set of read reference voltages is determined based on the ***overall threshold voltage distribution of all cells*** in flash memory

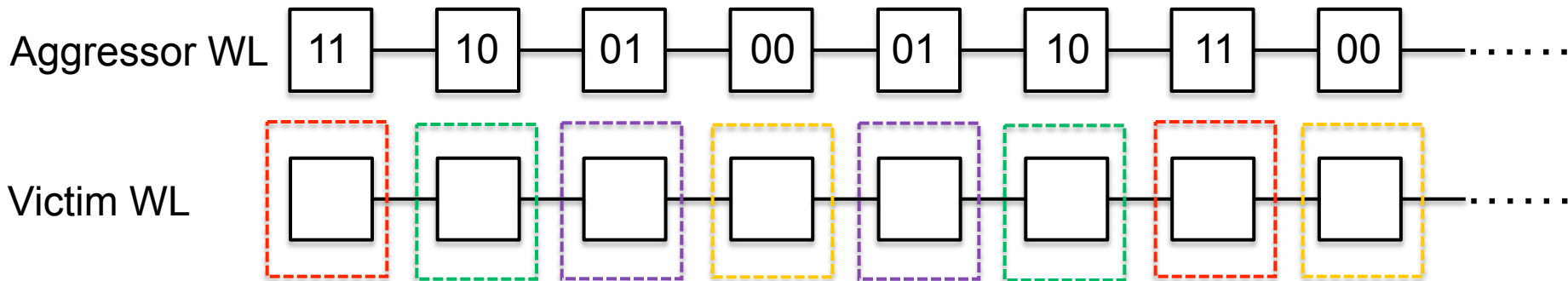
# New Observations [Cai+ SIGMETRICS'14]

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- Vth distributions of **cells with different-valued immediate-neighbor cells** are significantly different
  - Because neighbor value affects the amount of Vth shift
- **Corollary:** If we know the value of the immediate-neighbor, we can find a **more accurate set of read reference voltages** based on the “conditional” threshold voltage distribution

Cai et al., **Neighbor-Cell Assisted Error Correction for MLC NAND Flash Memories**, SIGMETRICS 2014.

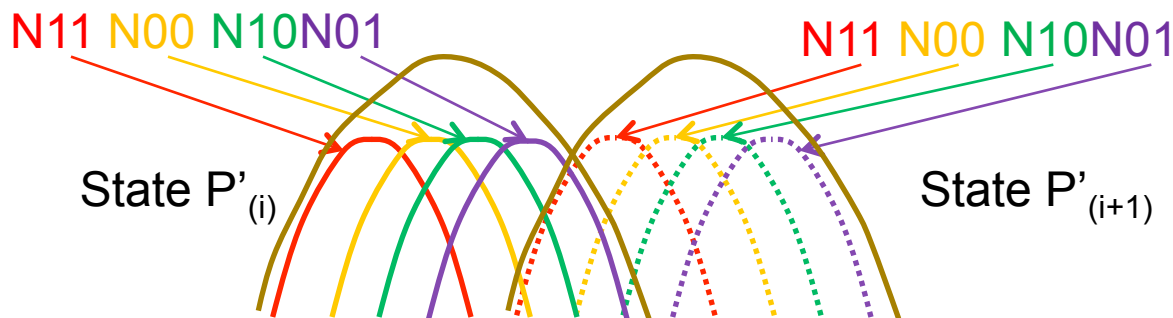
# Secrets of Threshold Voltage Distributions



Victim WL **before** MSB page of aggressor WL are programmed



Victim WL **after** MSB page of aggressor WL are programmed

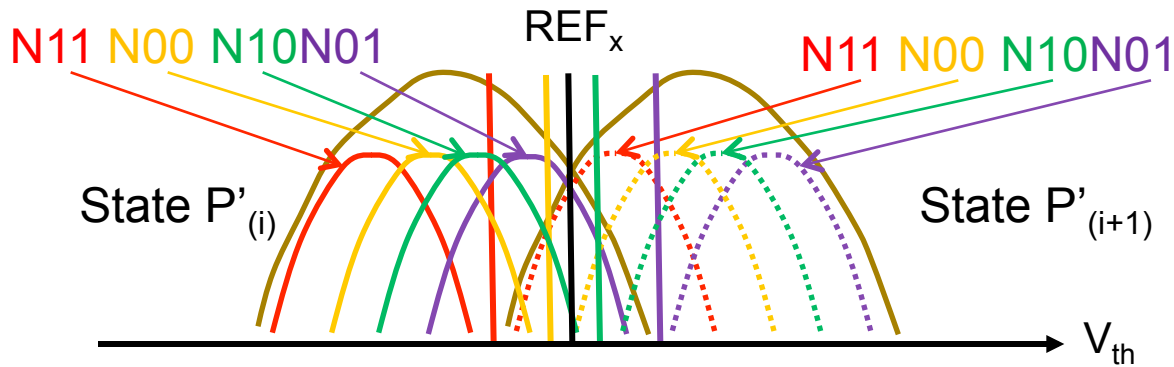


# If We Knew the Immediate Neighbor ...

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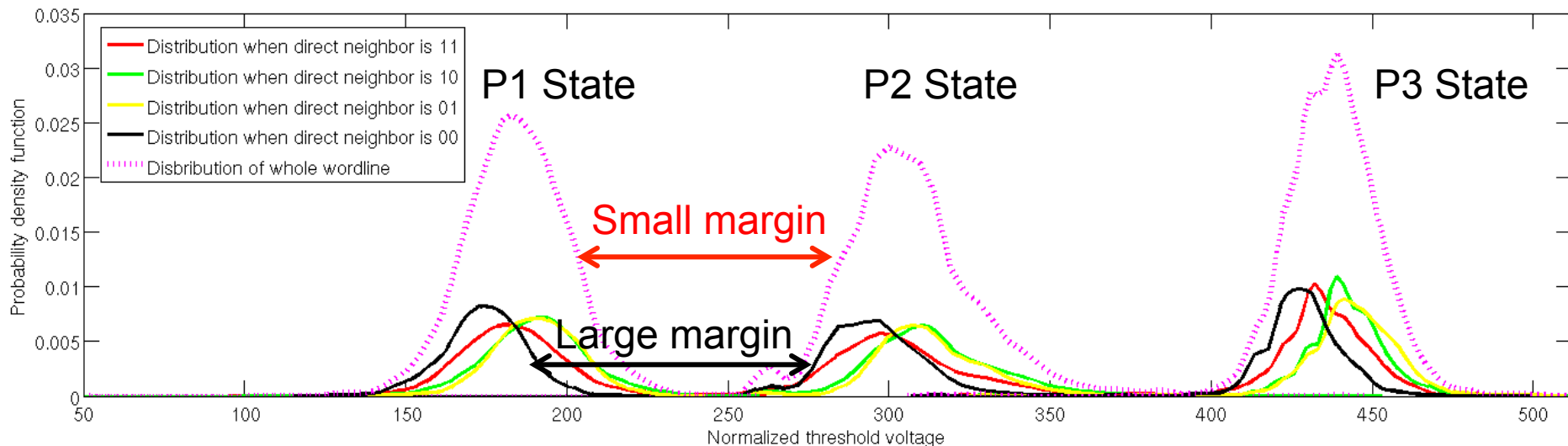
- Then, we could choose a different read reference voltage to more accurately read the “victim” cell

# Overall vs Conditional Reading



- Using the optimum read reference voltage based on the overall distribution leads to more errors
- Better to use the optimum read reference voltage based on the conditional distribution (i.e., value of the neighbor)
  - Conditional distributions of two states are farther apart from each other

# Measurement Results



	Overall	$x_{11}$ (ER)	$x_{10}$ (P1)	$x_{00}$ (P2)	$X_{01}$ (P3)
Distance	65.4	65.4	64.7	66.4	65.8
Variance	385.9	286.2	256.7	242.8	252.1
SNR	3.4	3.8	3.9	4.2	4.1
BER	$3 \times 10^{-4}$	$7 \times 10^{-5}$	$5 \times 10^{-5}$	$2 \times 10^{-5}$	$3 \times 10^{-5}$

**Raw BER of conditional reading is much smaller than overall reading**

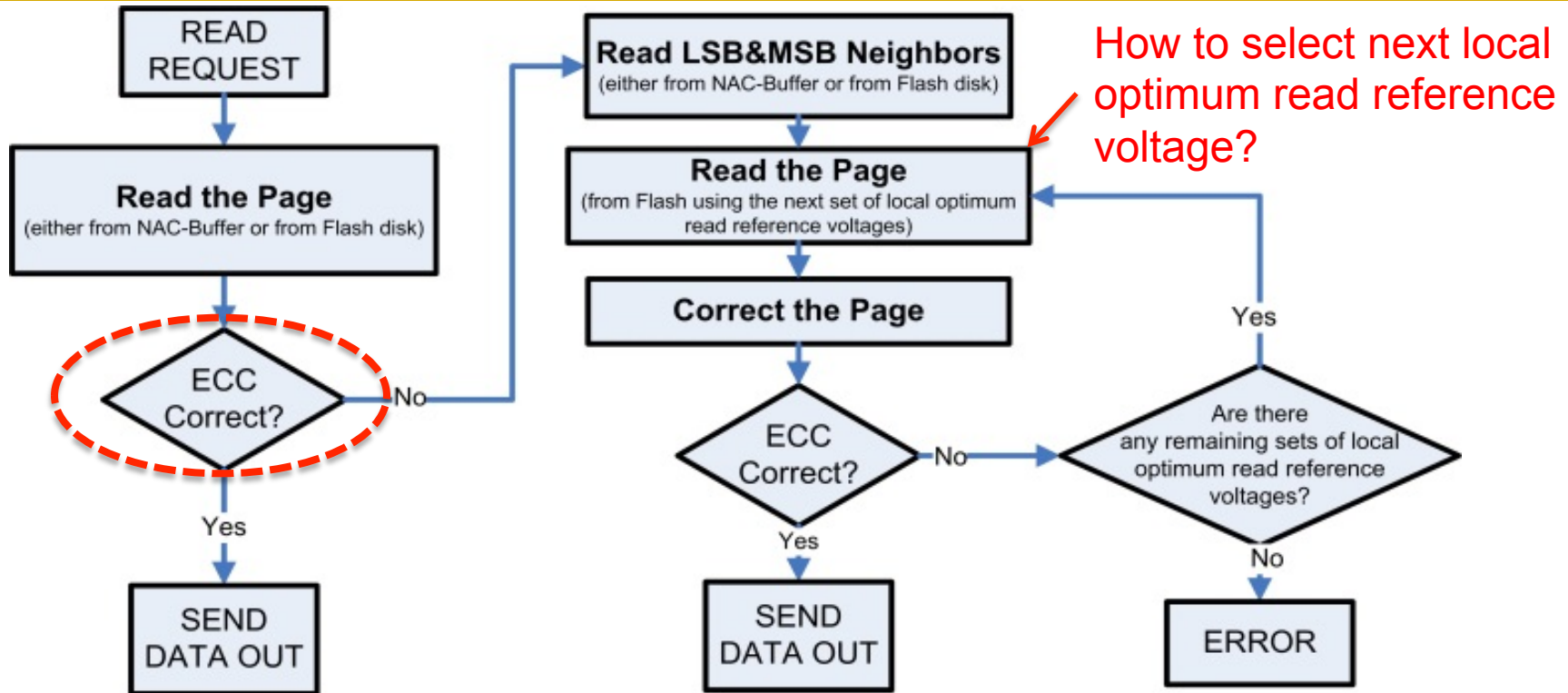
# Idea: Neighbor Assisted Correction (NAC)

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- Read a page with the read reference voltages based on overall  $V_{th}$  distribution (same as today) and buffer it
- If ECC fails:
  - Read the immediate-neighbor page
  - Re-read the page using the read reference voltages corresponding to the voltage distribution assuming a particular immediate-neighbor value
  - Replace the buffered values of the cells with that particular immediate-neighbor cell value
  - Apply ECC again

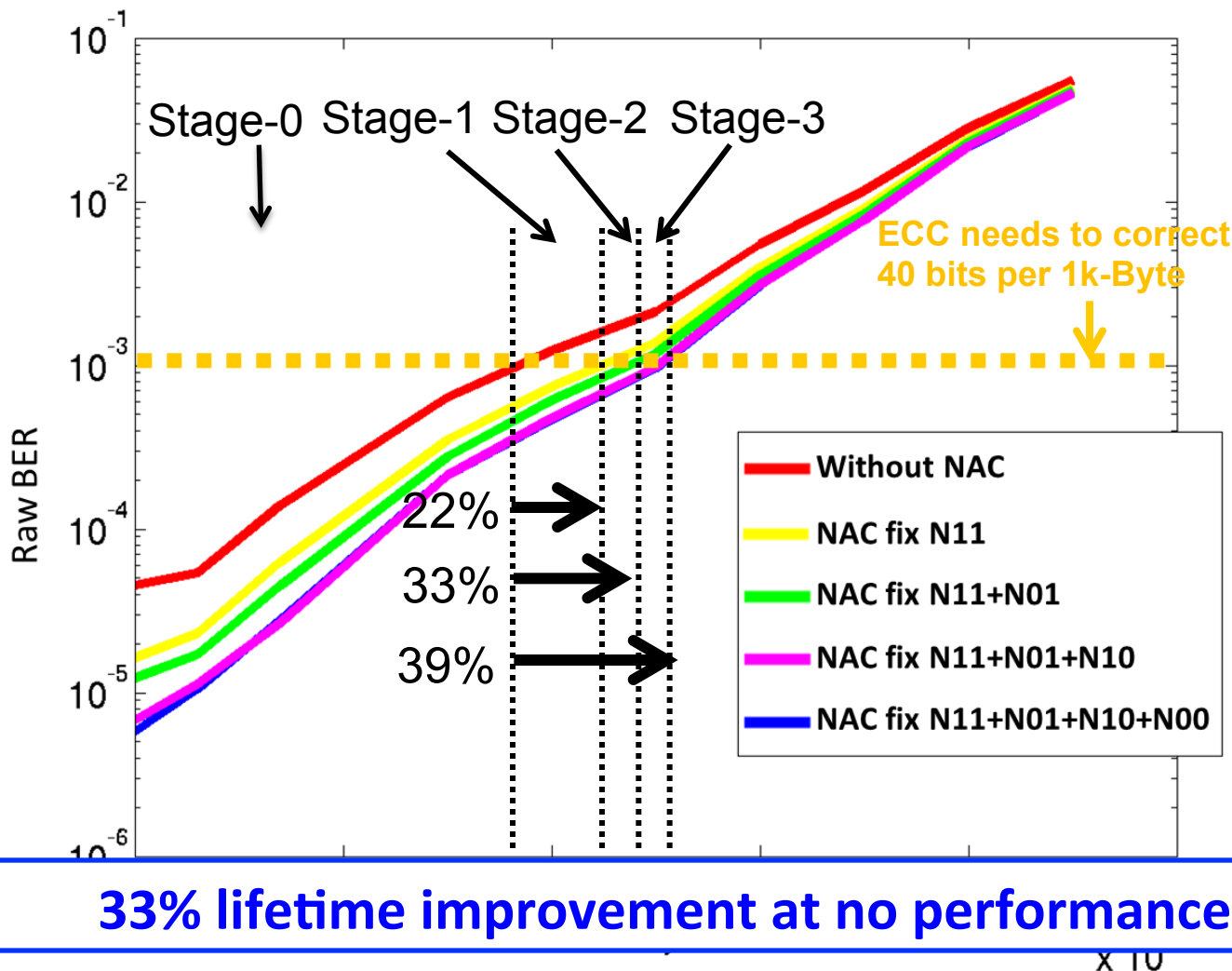


# Neighbor Assisted Correction Flow

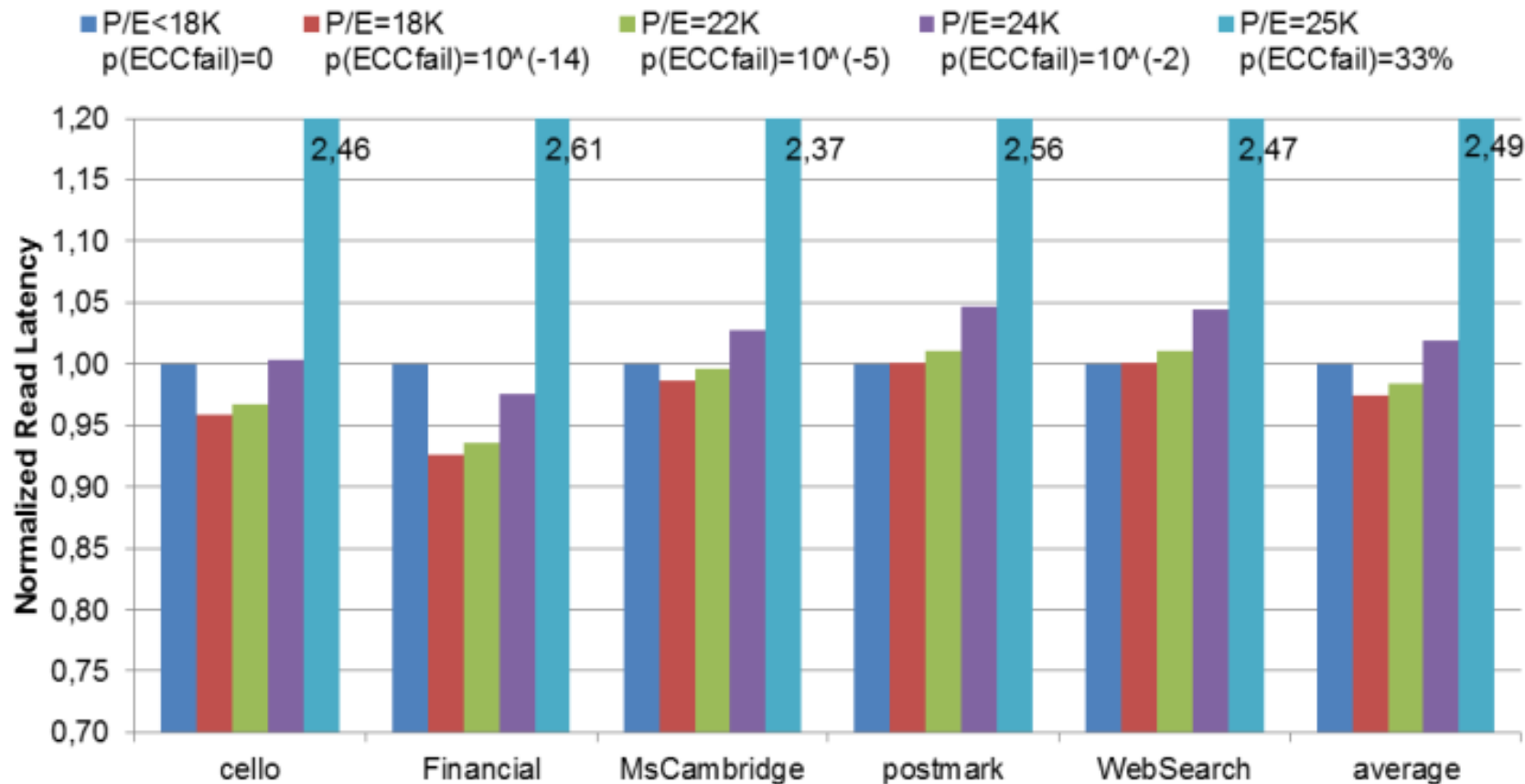


- Trigger neighbor-assisted reading only when ECC fails
- Read neighbor values and use corresponding read reference voltages in a prioritized order until ECC passes

# Lifetime Extension with NAC



# Performance Analysis of NAC



No performance loss within nominal lifetime  
and with reasonable (1%) ECC fail rates

- Yu Cai, Gulay Yalcin, Onur Mutlu, Eric Haratsch, Osman Unsal, Adrian Cristal, and Ken Mai,  
**"Neighbor-Cell Assisted Error Correction for MLC NAND Flash Memories"**  
*Proceedings of the  
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Modeling of Computer Systems (**SIGMETRICS**), Austin,  
TX, June 2014. Slides (ppt) (pdf)*

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- We are: (1) Building reliable error models for NAND flash memory via experimental characterization, (2) Developing efficient techniques to improve reliability and endurance
- This talk provided a “flash” summary of our recent results published in the past 3 years:
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**"Error Analysis and Retention-Aware Error Management for NAND Flash Memory"**  
*Intel Technology Journal (ITJ) Special Issue on Memory Resiliency*, Vol. 17, No. 1, May 2013.
- Yu Cai, Onur Mutlu, Erich F. Haratsch, and Ken Mai,  
**"Program Interference in MLC NAND Flash Memory: Characterization, Modeling, and Mitigation"**  
*Proceedings of the 31st IEEE International Conference on Computer Design (ICCD)*, Asheville, NC, October 2013. [Slides \(pptx\)](#) [\(pdf\)](#) [Lightning Session Slides \(pdf\)](#)
- Yu Cai, Gulay Yalcin, Onur Mutlu, Eric Haratsch, Osman Unsal, Adrian Cristal, and Ken Mai,  
**"Neighbor-Cell Assisted Error Correction for MLC NAND Flash Memories"**  
*Proceedings of the ACM International Conference on Measurement and Modeling of Computer Systems (SIGMETRICS)*, Austin, TX, June 2014. [Slides \(ppt\)](#) [\(pdf\)](#)



# Referenced Papers

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- All are available at <http://users.ece.cmu.edu/~omutlu/projects.htm>

- **Computer Architecture Lecture Videos on Youtube**
  - <https://www.youtube.com/playlist?list=PL5PHm2jkkXmidJOd59REog9jDnPDTG6IJ>
- **Computer Architecture Course Materials**
  - <http://www.ece.cmu.edu/~ece447/s13/doku.php?id=schedule>
- **Advanced Computer Architecture Course Materials**
  - <http://www.ece.cmu.edu/~ece740/f13/doku.php?id=schedule>
- **Advanced Computer Architecture Lecture Videos on Youtube**
  - [https://www.youtube.com/playlist?list=PL5PHm2jkkXmgDN1PLwOY\\_tGtUlyunnyV6D](https://www.youtube.com/playlist?list=PL5PHm2jkkXmgDN1PLwOY_tGtUlyunnyV6D)

Thank you.

Feel free to email me with any questions & feedback

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# Error Analysis and Management for MLC NAND Flash Memory

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(joint work with Yu Cai, Gulay Yalcin, Eric Haratsch, Ken Mai, Adrian Cristal, Osman Unsal)

August 7, 2014

Flash Memory Summit 2014, Santa Clara, CA

# Additional Slides

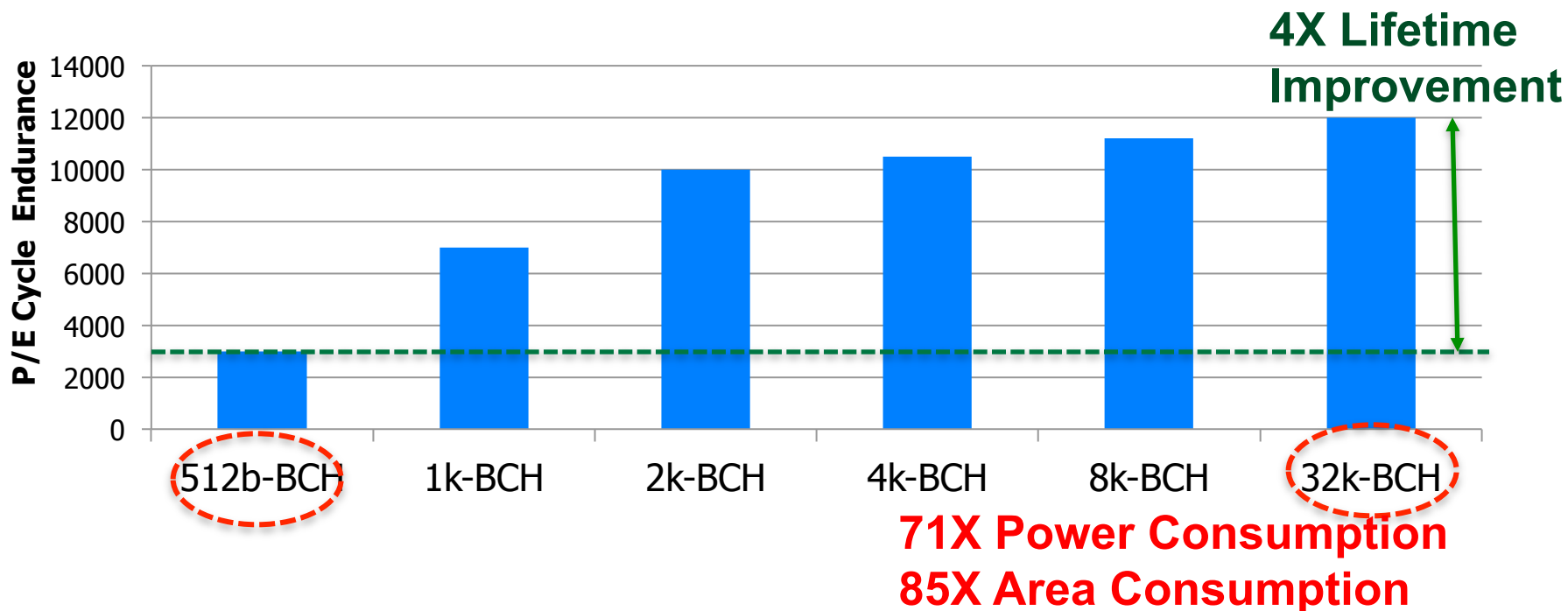
# Error Types and Testing Methodology

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- Erase errors
  - Count the number of cells that fail to be erased to “11” state
  
- Program interference errors
  - Compare the data immediately after page programming and the data after the whole block being programmed
  
- Read errors
  - Continuously read a given block and compare the data between consecutive read sequences
  
- Retention errors
  - Compare the data read after an amount of time to data written
    - Characterize short term retention errors under room temperature
    - Characterize long term retention errors by baking in the oven under 125°C

# Improving Flash Lifetime with Strong ECC

- Lifetime improvement comparison of various BCH codes



Strong ECC is very inefficient at improving lifetime

Develop new techniques  
to improve flash lifetime  
without relying on stronger ECC

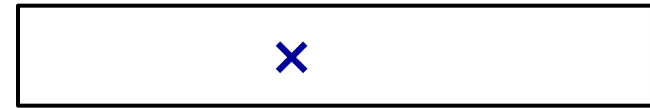
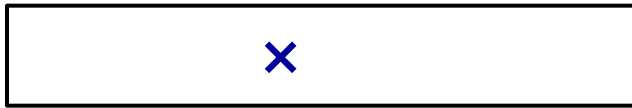


# FCR Intuition

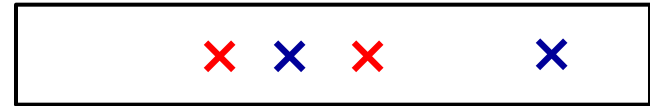
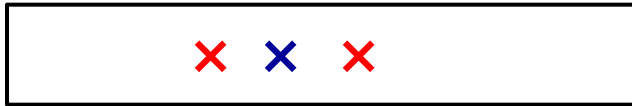
Errors with  
No refresh

Errors with  
Periodic refresh

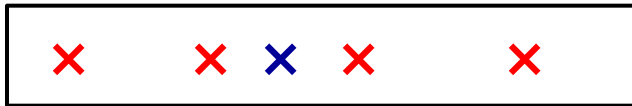
Program  
Page



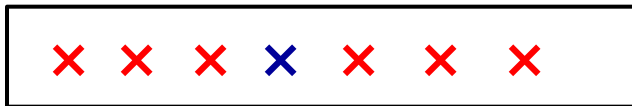
After  
time T



After  
time 2T



After  
time 3T

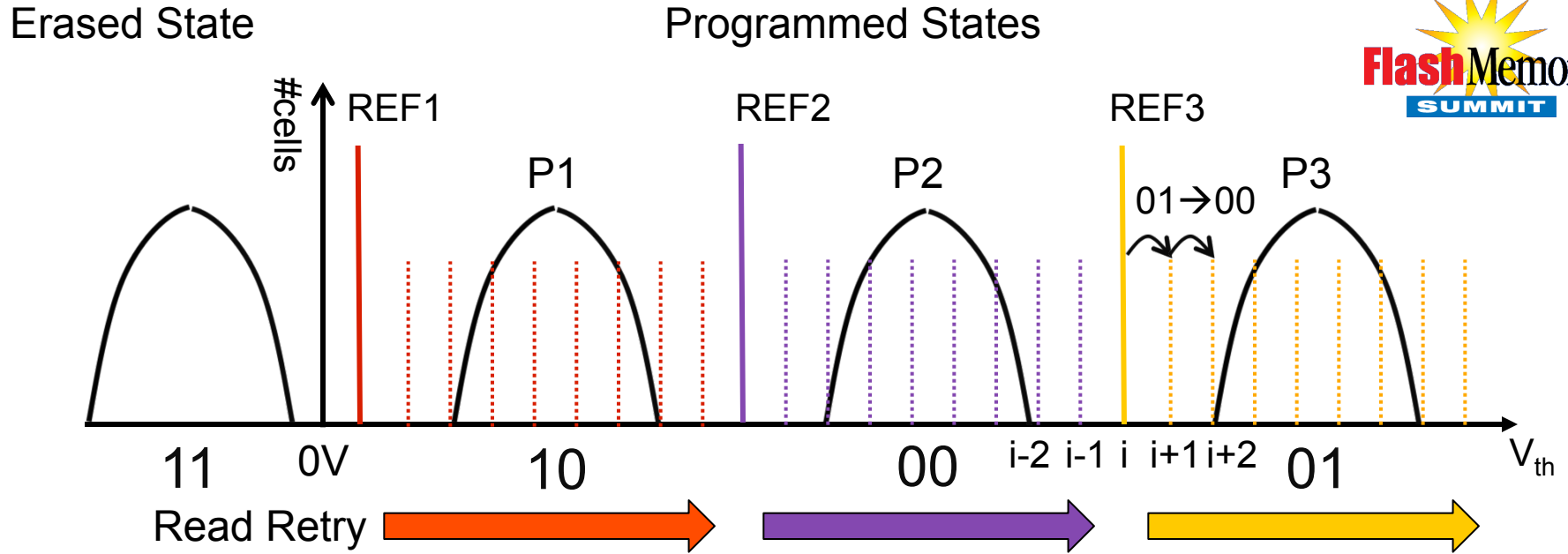


**X Retention Error**    **X Program Error**

# FCR Lifetime Evaluation Takeaways



- Significant average lifetime improvement over no refresh
  - Adaptive-rate FCR: 46X
  - Hybrid reprogramming/remapping based FCR: 31X
  - Remapping based FCR: 9X
- FCR lifetime improvement larger than that of stronger ECC
  - 46X vs. 4X with 32-kbit ECC (over 512-bit ECC)
  - FCR is less complex and less costly than stronger ECC
- Lifetime on all workloads improves with Hybrid FCR
  - Remapping based FCR can degrade lifetime on read-heavy WL
  - Lifetime improvement highest in write-heavy workloads



- **Read-retry feature of new NAND flash**
  - Tune read reference voltage and check which  $V_{th}$  region of cells
- **Characterize the threshold voltage distribution of flash cells in programmed states through Monte-Carlo emulation**



- **Parametric distribution**

- Closed-form formula, only a few number of parameters to be stored

- **Exponential distribution family**

Distribution parameter vector

$$p(\mathbf{x}|\boldsymbol{\eta}) = h(\mathbf{x})g(\boldsymbol{\eta}) \exp \left\{ \boldsymbol{\eta}^T \mathbf{u}(\mathbf{x}) \right\}$$

- **Maximum likelihood estimation (MLE) to learn parameters**

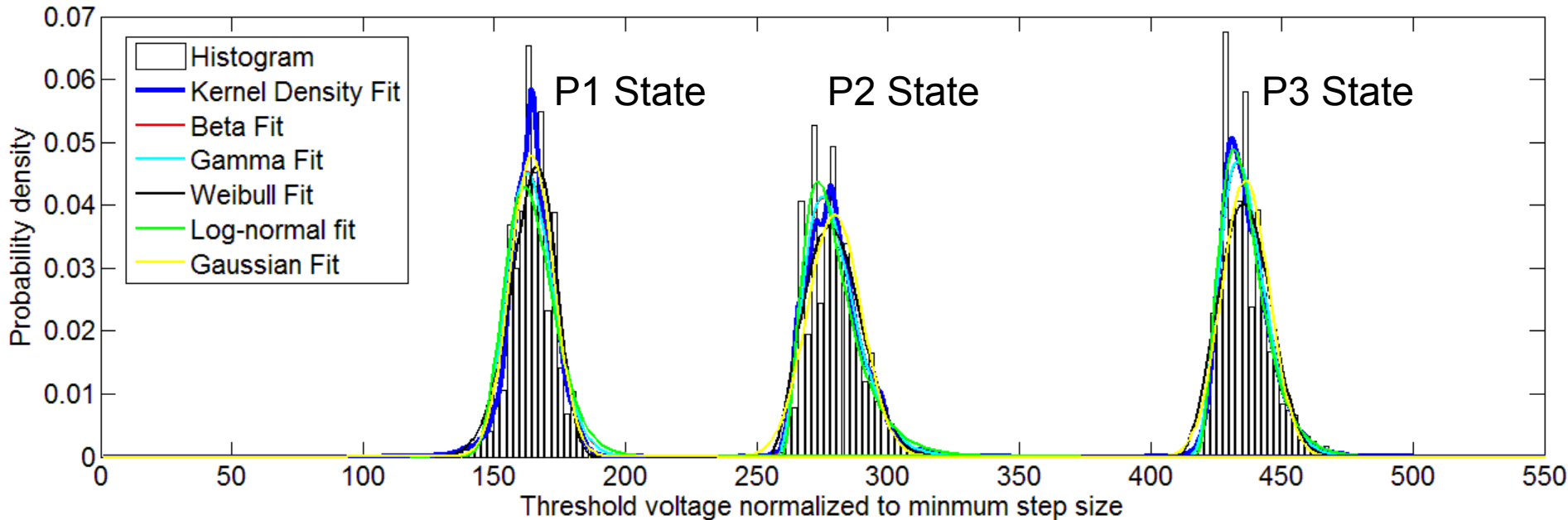
Observed testing data

Likelihood Function

$$p(\mathbf{X}|\boldsymbol{\eta}) = \left( \prod_{n=1}^N h(\mathbf{x}_n) \right) g(\boldsymbol{\eta})^N \exp \left\{ \boldsymbol{\eta}^T \sum_{n=1}^N \mathbf{u}(\mathbf{x}_n) \right\}$$

**Goal of MLE:** Find distribution parameters to maximize likelihood function

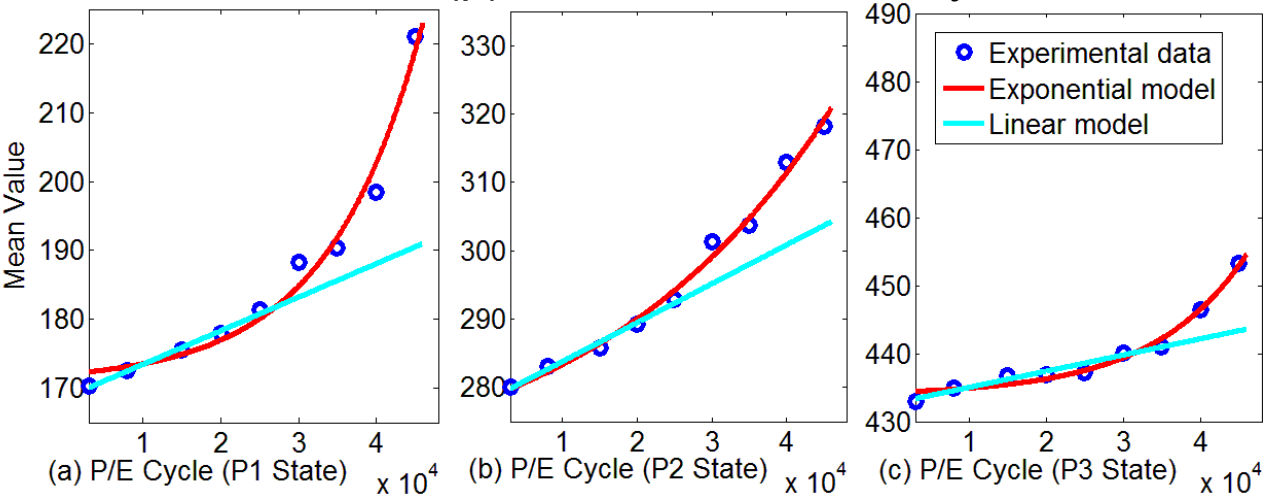
	Distribution $p(x   \eta)$	Parameters
Gaussian	$\frac{1}{\sigma\sqrt{2\pi}} \exp\left\{-\frac{1}{2}\left(\frac{x-\mu}{\sigma}\right)^2\right\}$	Mean: $\mu$ Var: $\sigma^2$
Beta	$\frac{\Gamma(\alpha + \beta)}{\Gamma(\alpha)\Gamma(\beta)} x^{\alpha-1} (1-x)^{\beta-1}$	Mean: $\alpha/(\alpha+\beta)$ Var: $\alpha\beta/((\alpha+\beta)^2(\alpha+\beta+1))$
Gamma	$\frac{1}{\theta^k} \frac{1}{\Gamma(k)} x^{k-1} e^{-\frac{x}{\theta}}$	Mean: $k\theta$ Var: $k\theta^2$
Log-normal	$\frac{1}{x\sigma\sqrt{2\pi}} \exp\left\{-\frac{(\ln x - \mu)^2}{2\sigma^2}\right\}$	Mean: $\exp(\mu + \sigma^2/2)$ Var: $(\exp(\sigma^2) - 1)\exp(2\mu + \sigma^2)$
Weibull	$\frac{k}{\lambda} \left(\frac{x}{\lambda}\right)^{k-1} \exp\left\{-\left(\frac{x}{\lambda}\right)^k\right\}$	Mean: $\lambda\Gamma(1+1/k)$ Var: $\lambda^2\Gamma(1+2/k) - \mu^2$



	Beta	Gamma	Gaussian	Log-normal	Weibull
RMSE	19.5%	20.3%	22.1%	24.8%	28.6%

**Distribution can be approx. modeled as Gaussian distribution**

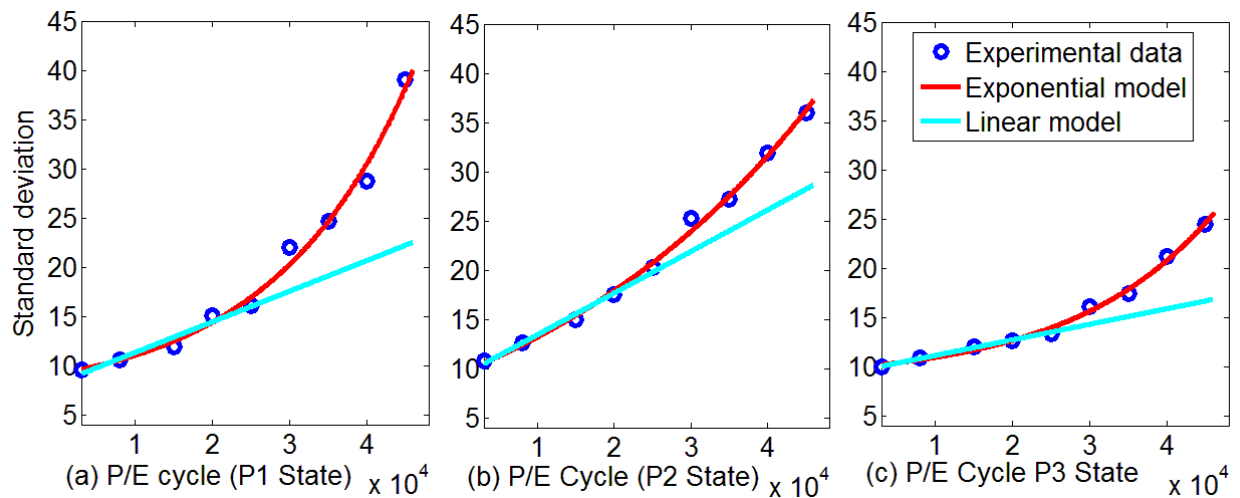
## Mean value ( $\mu$ ) increases with P/E cycles



Exponential model

$$V_{th}^{mean,std}(PEcycle) = A + B \times e^{C \times PEcycle}$$

## Standard deviation value ( $\sigma$ ) increases with P/E cycles



Linear model

$$V_{th}^{mean,std}(PEcycle) = D + E \times PEcycle$$



- **P/E operations modeled as signal passing thru AWGN channel**
  - Approximately Gaussian with 22% distortion
  - P/E noise is white noise
- **P/E cycling noise affects threshold voltage distributions**
  - Distribution shifts to the right and widens around the mean value
  - Statistics (mean/variance) can be modeled as exponential correlation with P/E cycles with 95% accuracy
- **Future work**
  - Characterization and models for retention noise
  - Characterization and models for program interference noise



# Program Interference: Key Findings

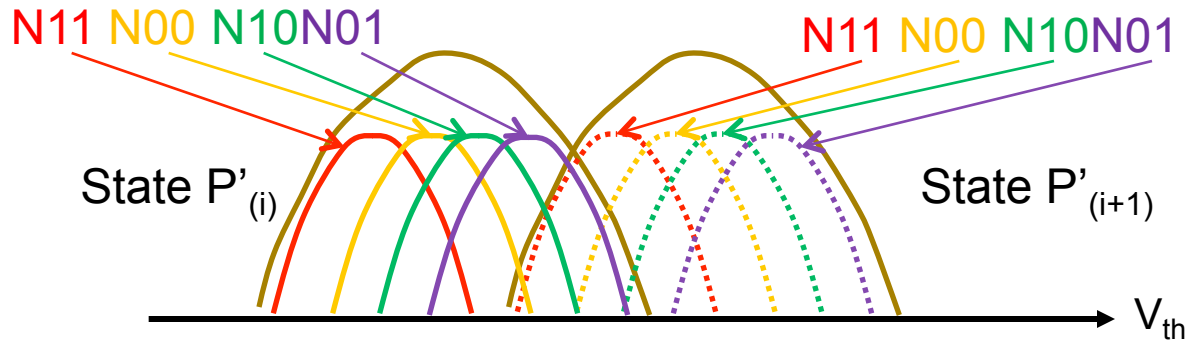
- **Methodology:** Extensive experimentation with real 2Y-nm MLC NAND Flash chips
- Amount of **program interference is dependent on**
  - **Location** of cells (programmed and victim)
  - **Data values** of cells (programmed and victim)
  - **Programming order** of pages
- Our **new model** can predict the amount of program interference with 96.8% prediction accuracy
- Our **new read reference voltage prediction technique** can improve flash lifetime by 30%

# NAC: Executive Summary



- **Problem:** Cell-to-cell Program interference causes threshold voltage of flash cells to be distorted even they are originally programmed correctly
- **Our Goal:** Develop techniques to overcome cell-to-cell program interference
  - ❑ Analyze the threshold voltage distributions of flash cells *conditionally upon the values of immediately neighboring cells*
  - ❑ Devise new error correction mechanisms that can *take advantage of the values of neighboring cells* to reduce error rates over conventional ECC
- **Observations:** Wide overall distribution can be decoupled into multiple narrower conditional distributions which can be separated easily
- **Solution:** Neighbor-cell Assisted Correction (NAC)
  - ❑ Re-read a flash memory page that initially failed ECC with a set of read reference voltages corresponding to the conditional threshold voltage distribution
  - ❑ Use the re-read values to correct the cells that have neighbors with that value
  - ❑ Prioritize reading assuming neighbor cell values that cause largest or smallest cell-to-cell interference to allow ECC correct errors with less re-reads
- **Results:** NAC improves flash memory lifetime by 39%
  - ❑ **Within nominal lifetime:** no performance degradation
  - ❑ **In extended lifetime:** less than 5% performance degradation

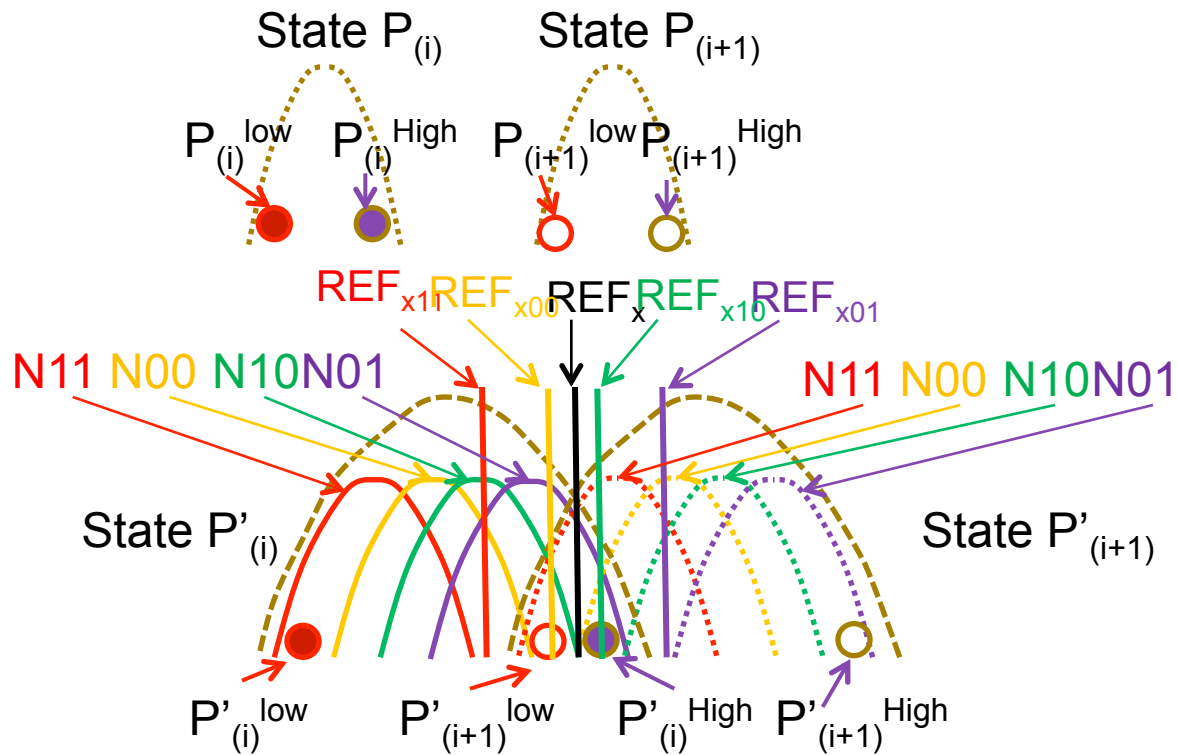
# Overall vs Conditional V<sub>th</sub> Distributions



- Overall distribution:  $p(x)$
- Conditional distribution:  $p(x, z=m)$ 
  - $m$  could be 11, 00, 10 and 01 for 2-bit MLC all-bit-line flash
- Overall distribution is the sum of all conditional distributions

$$p(x) = \sum_{m=1}^{2^n} p(x, z = m)$$

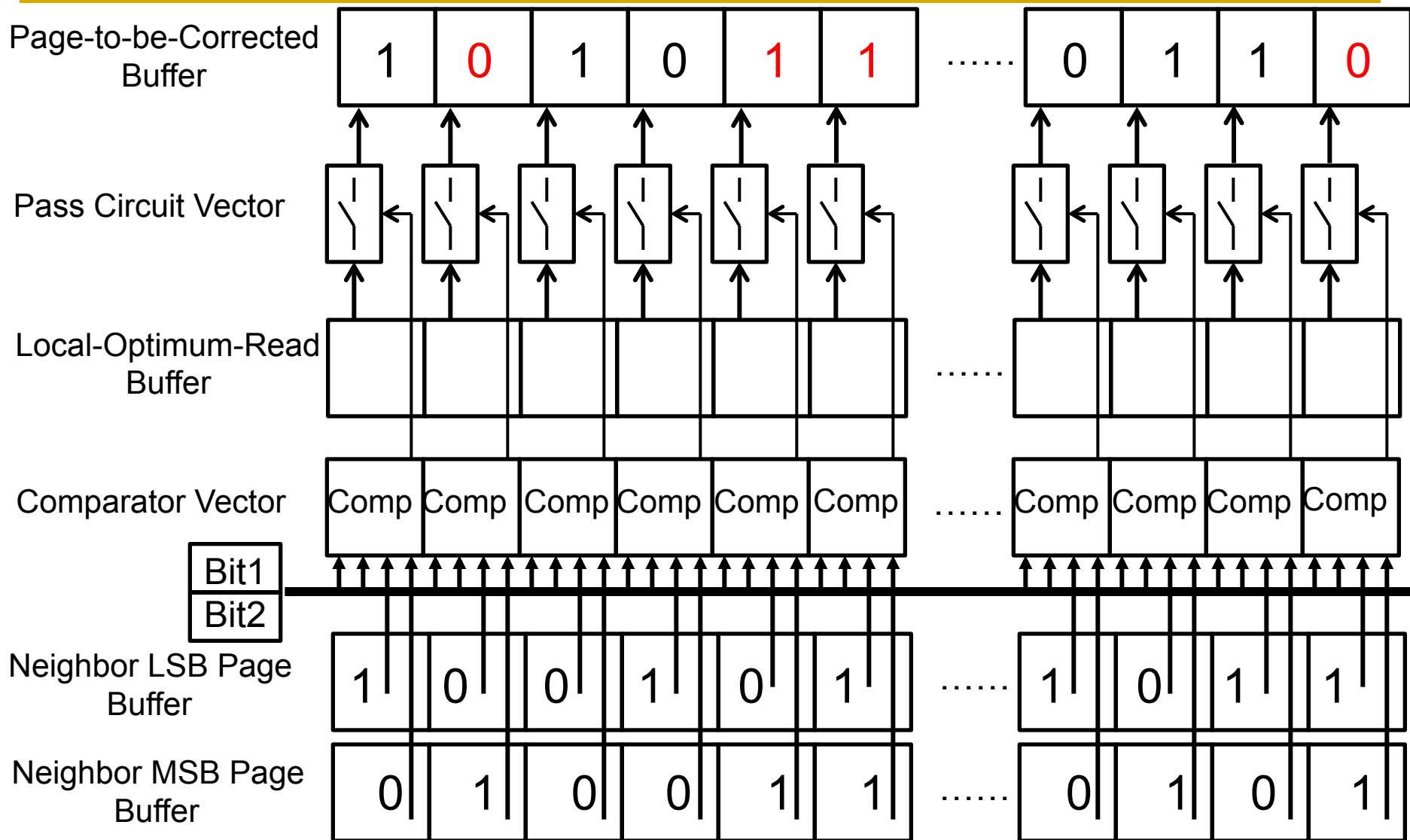
# Prioritized NAC



- Dominant errors are caused by the overlap of lower state interfered by high neighbor interference and the higher state interfered by low neighbor interference

- Online learning
  - Periodically (e.g., every 100 P/E cycles) measure and learn the overall and conditional threshold voltage distribution statistics (e.g. mean, standard deviation and corresponding optimum read reference voltage)
- NAC procedure
  - Step 1: Once ECC fails reading with overall distribution, load the failed data and corresponding neighbor LSB/MSB data into NAC
  - Step 2: Read the failed page with the local optimum read reference voltage for cells with neighbor programmed as 11
  - Step 3: Fix the value for cells with neighbor 11 in step 1
  - Step 4: Send fixed data for ECC correction. If succeed, exit. Otherwise, go to step 2 and try to read with the local optimum read reference voltage 10, 01 and 00 respectively

# Microarchitecture of NAC (Initialization)



# NAC (Fixing cells with neighbor 11)

